

Applied (High Temperature) Superconductivity

Academic Training Lecture 3

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Outline for the week of training

- Lectures 1& 2: Introduction & “Just enough” physics
 - Brief introduction ... what is superconductivity and why is it useful?
 - Basic physics of superconductivity and the superconducting state
 - Applications-relevant physics of superconductivity & superconducting state
- **Lecture 3: Technical superconductors**
 - What a magnet wants
 - A brief summary of NbTi and Nb₃Sn
 - HTS conductor options: Bi2212 & YBCO
- Lecture 4: Electromechanical behavior
 - A brief summary of NbTi and Nb₃Sn
 - HTS conductor options: Bi2212 & YBCO
- Lecture 5: Quench behavior and high field magnets
 - What is quench protection?

What a magnet wants... magnet engineering issues

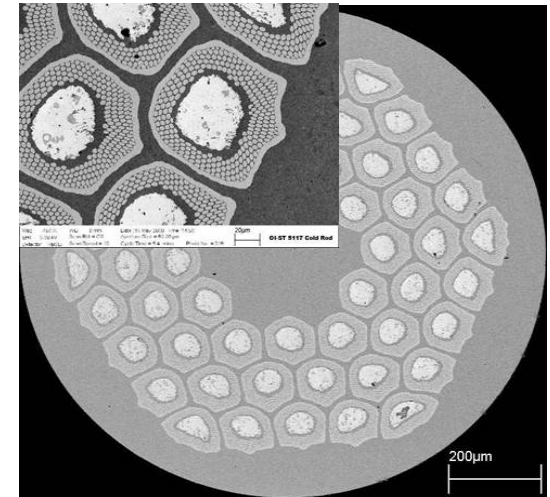
- Conductor ... the bridge from phenomenon to magnets
 - Availability & Cost
 - Processing & manufacturing (nano → macro)
 - J_c at field, temperature, field orientation ... application driven
 - Uniformity
 - Chemical compatibility with reinforcement and insulation
 - Conductor size and scalability
 - Multifilamentary
 - Cable-able
- *Stability & quench protection*
- Magnet fabrication
- *Electromechanical behavior*
- AC losses
- Turn-to-turn insulation
- Cooling
- Joints

Desirable Conductor Properties

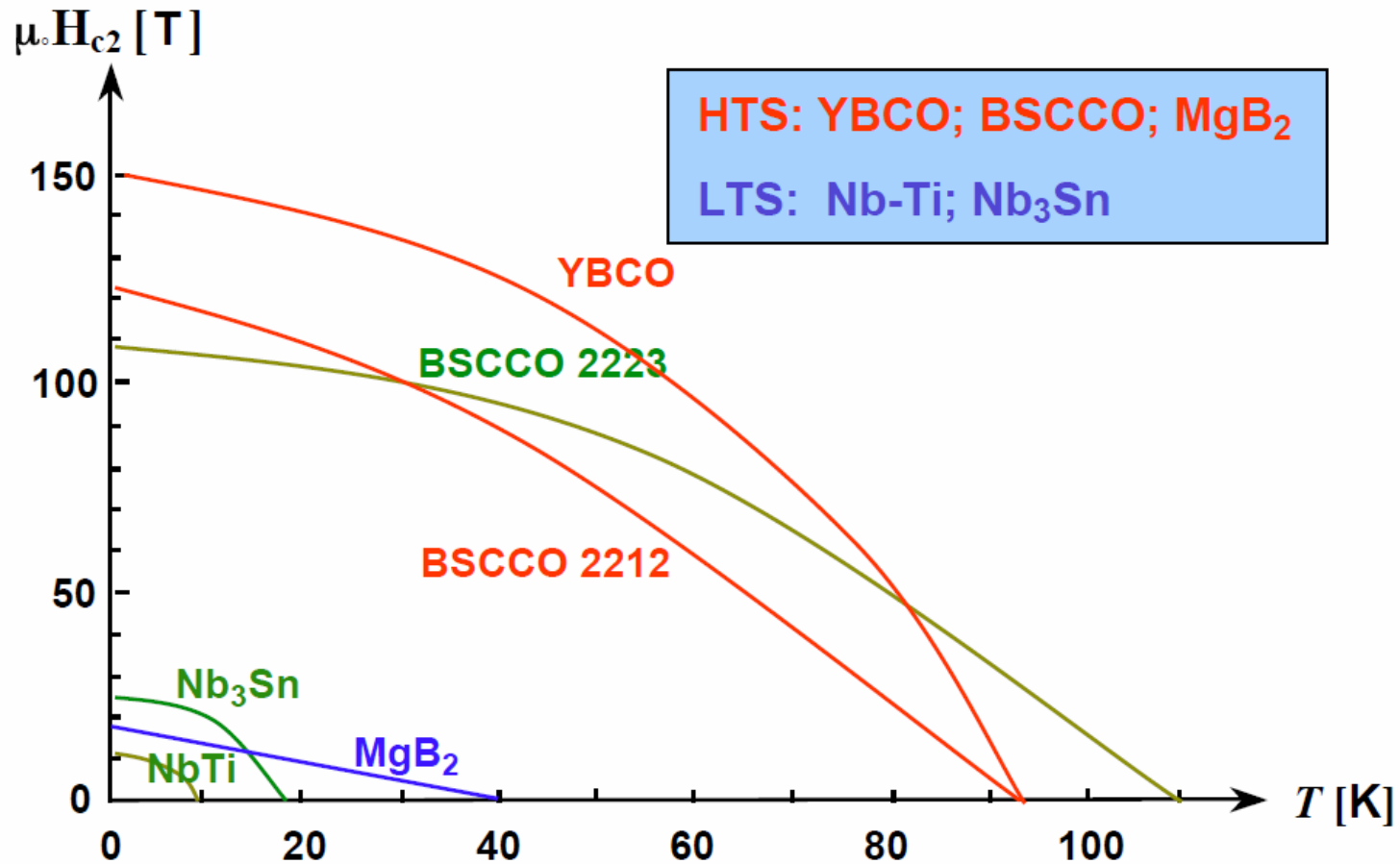
- $J_c(B)$ 1st & foremost; but other properties can be limiting
- Mechanical properties
 - High strength and modulus (strain tolerant)
 - Workability during processing (ductility)
 - Effect of strain on superconducting properties
- Environmental properties
 - atmosphere (H_2O , other components to magnet)
 - thermal contraction effects ($\Delta L/L$)
 - radiation effects (fusion and accelerator applications)
- Costs
 - much of cost is in processing, handling
 - NbTi ~ \$100/lb, Nb₃Sn ~ \$1000/lb, Ag/Bi2212 ~ \$20/meter, YBCO conductor ~ \$50/meter

Two (or three) types of Type II superconductors

- “Low- T_c superconductors” (LTS)
 - NbTi and Nb₃Sn
 - Commercially available
 - In most operating superconducting magnets
 - Conductors are predominantly Cu
- “High- T_c superconductors” (HTS)
 - Discovered from 1986-1993 with much fanfare
 - Bi₂Sr₂CaCu₂O_{8+y} & YBa₂Cu₃O_{7-x} are most technically interesting
 - ***more complicated than LTS in almost every way***
 - flux motion is thermally activated ... now T-window is wider
 - complex multicomponent oxide
 - very small ξ → grain boundaries are weak-links
 - highly anisotropic structure & properties
- MgB₂ not quite LTS or HTS. Might become useful too.



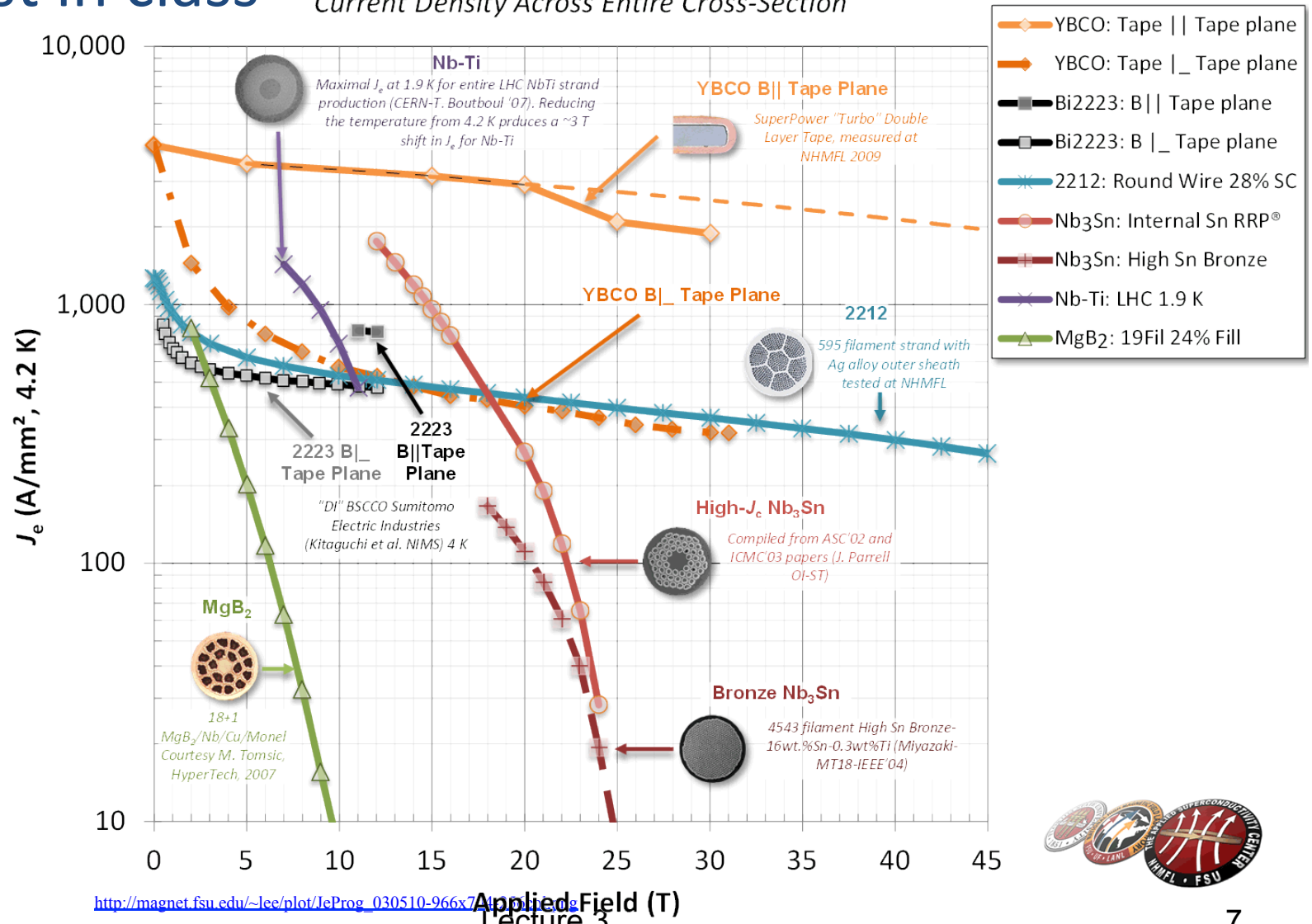
Upper critical field versus temperature



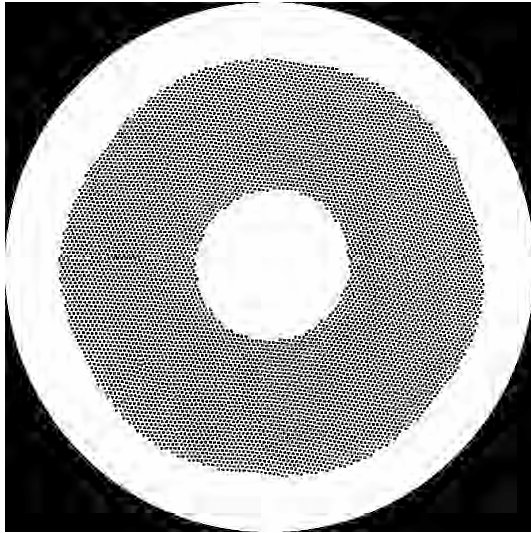
Critical current density versus magnetic field

“best in class”

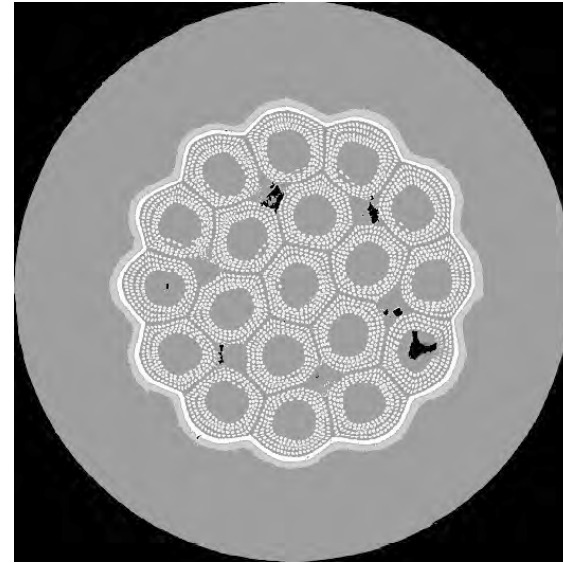
Current Density Across Entire Cross-Section



LTS conductors are highly engineered, complex composites



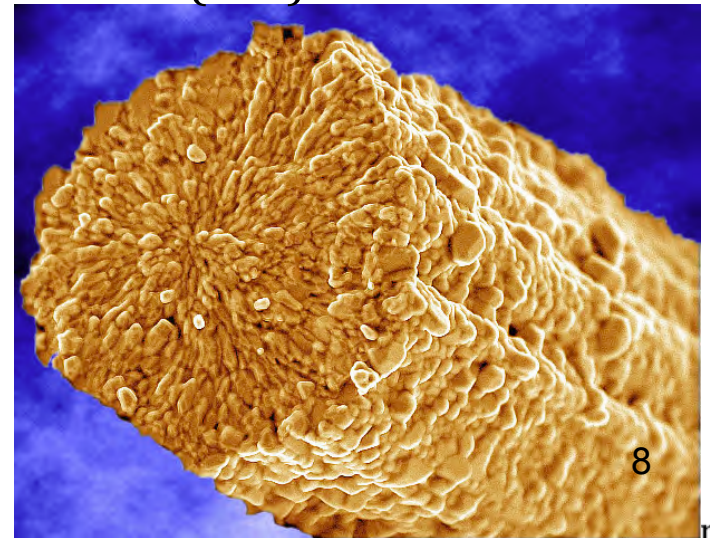
Typical SSC Nb-47wt.%Ti strand (OST)



Typical reacted ITER Nb₃Sn strand (IGC)



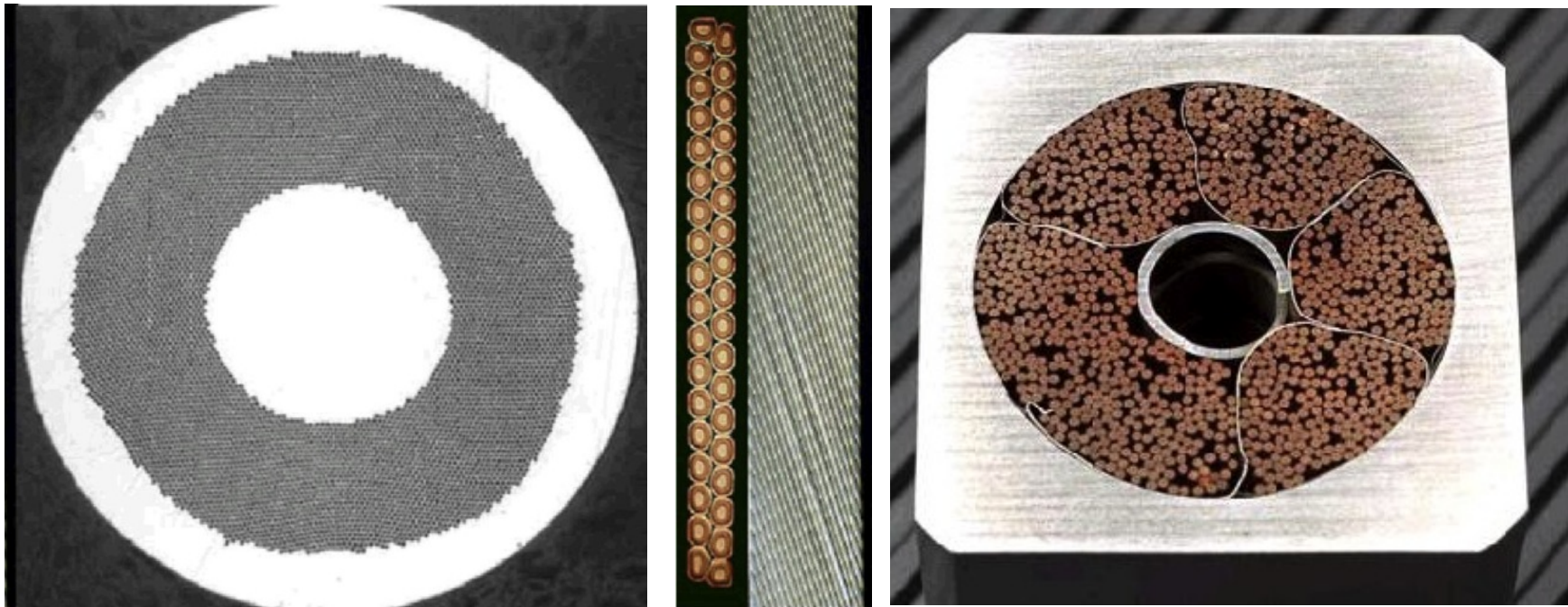
20 μm



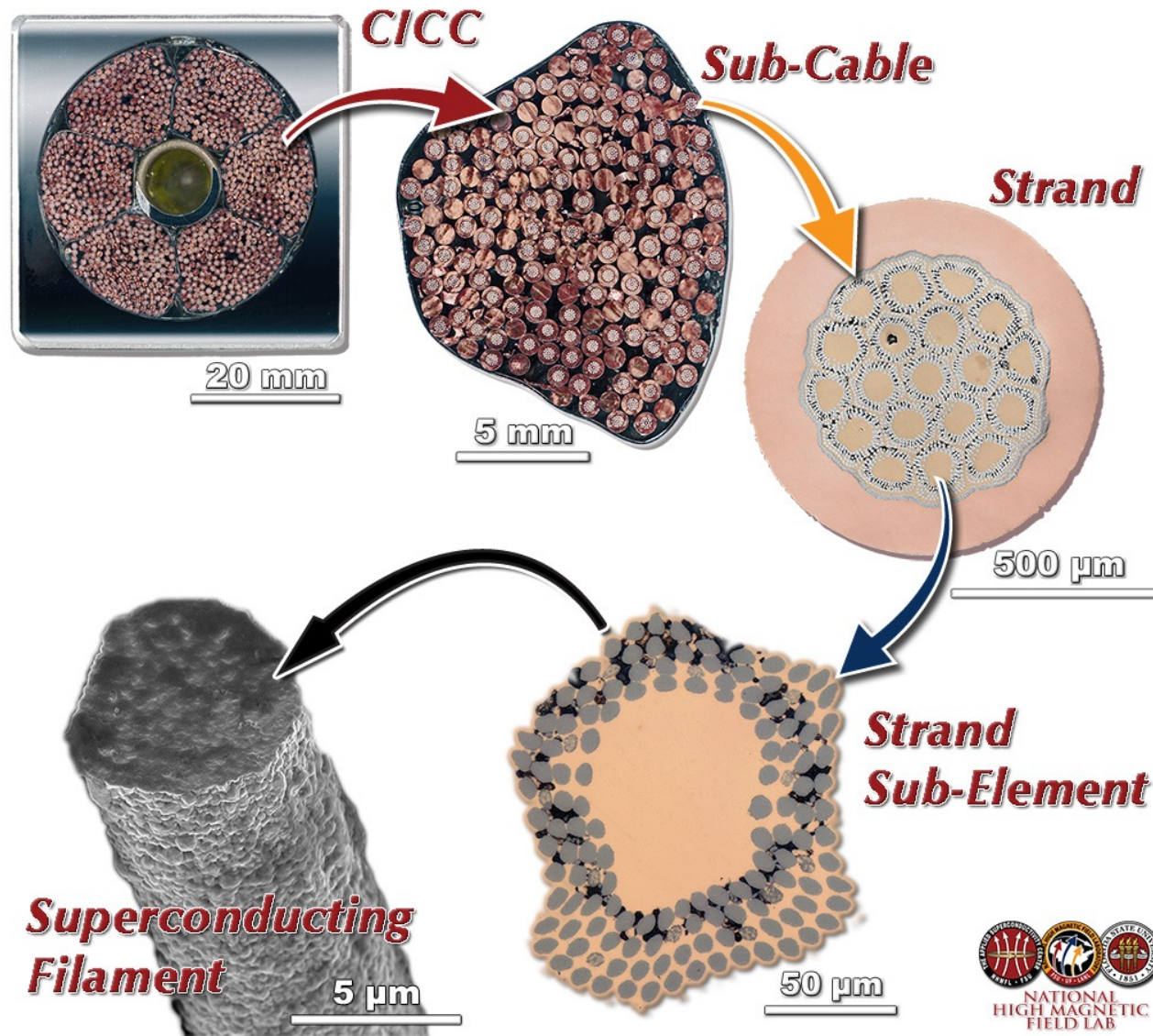
8

Conductors for magnets – strand and cable

- Magnets can be from strand (wire) or cable
- Decision driven by the demand of the application
- Cables vary greatly depending on what is required



Length scales (this example is Nb₃Sn)



NbTi Alloys as Superconductors

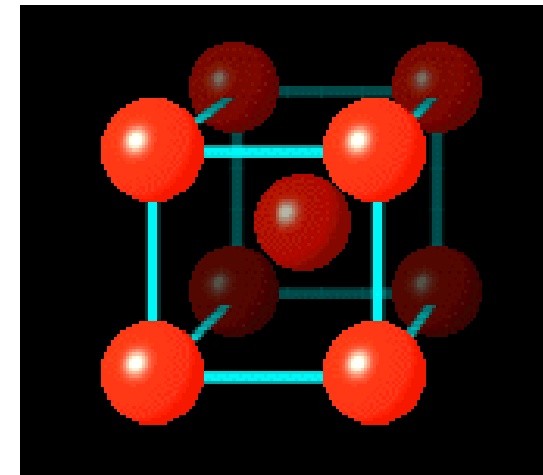
- First discovered in early 1960s that Nb formed continuous solution alloy with Zr, other elements
- Technologically/commercially matured by the Tevatron
- Became “stock” material by medical MRI

ve-	3	4	5	6	7
3d	Sc	Ti	V	Cr	Mn
4d	Y	Zr	Nb	Mo	Tc
5d	La	Hf	Ta	W	Re

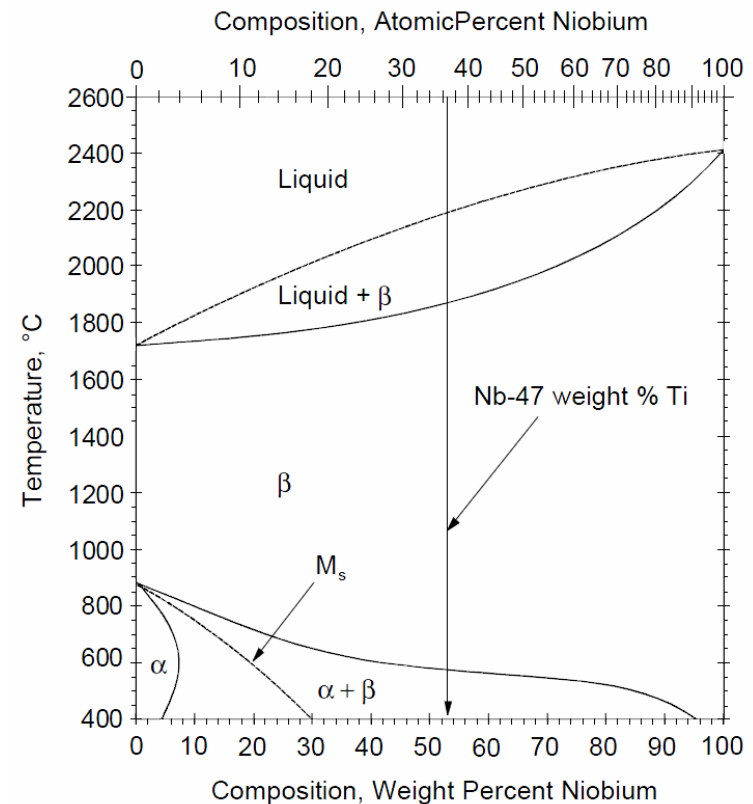
4-5 transition elements

NbTi wires

- Nb and Ti are soluble & at high temperature form a ductile alloy: β phase
- Cold work & heat treatment determines the formation of other phases
- α phase is used for flux pinning
- Easily processed by extrusion and drawing
- J_c depends on the microstructure
- Mature product: ~3 Ton per day for MRI, ~60,000 km/year
- Cost ~\$1/kA·m (Cu ~\$20/kA·m)



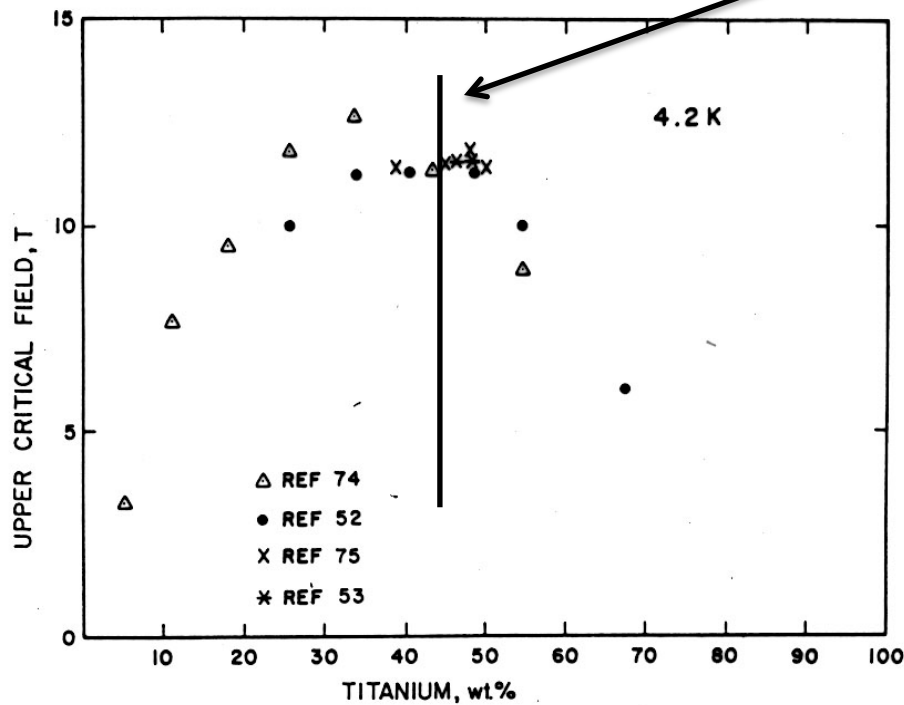
BCC crystal structure



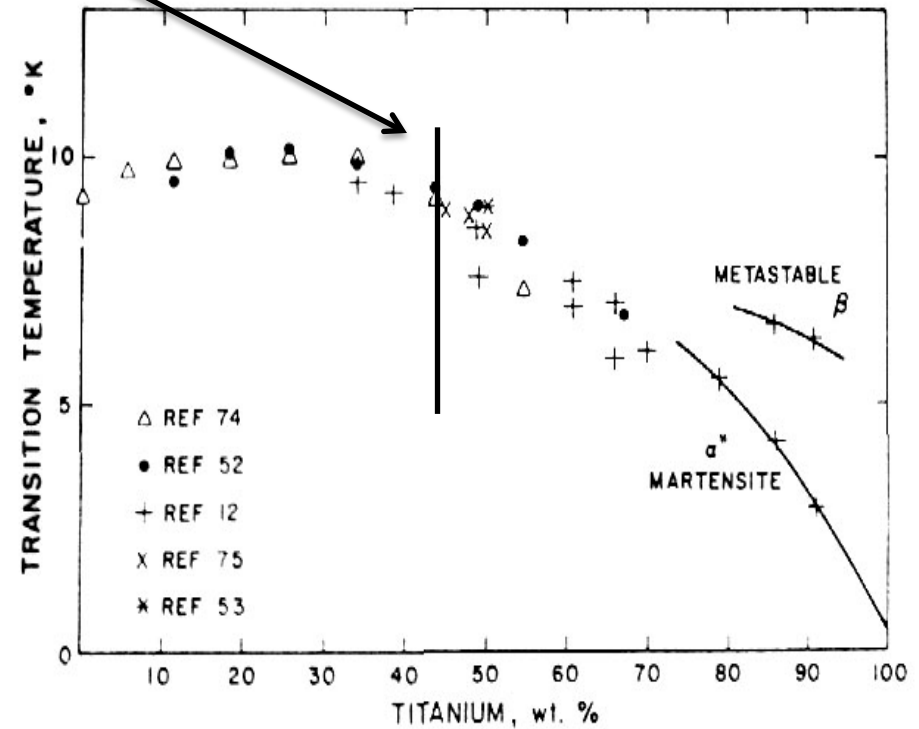
Lecture 3

NbTi: H_{c2} and T_c vary with composition

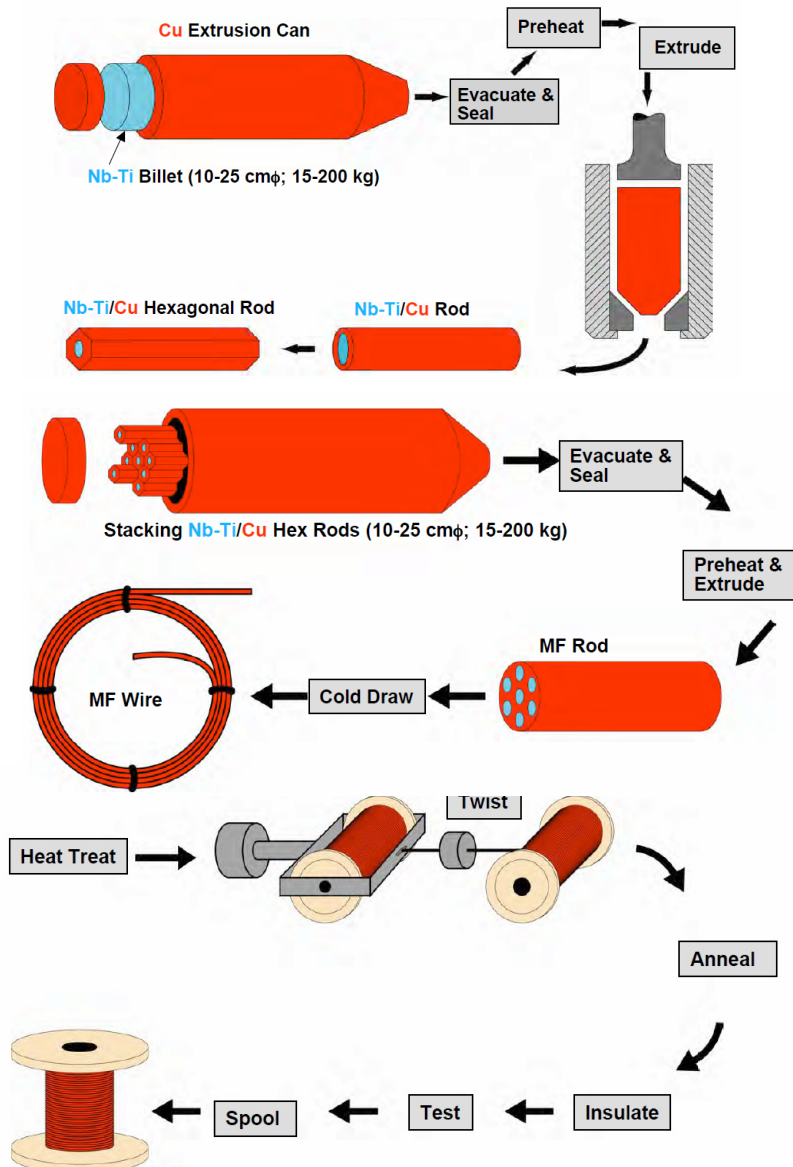
Commercial material not at either peak



Upper critical field of Nb-Ti alloys at 4.2 K.



Fabrication of NbTi wire



Stage I: Stacking & Hexagonal
Nb-Ti/Cu Rod
monofilament composite

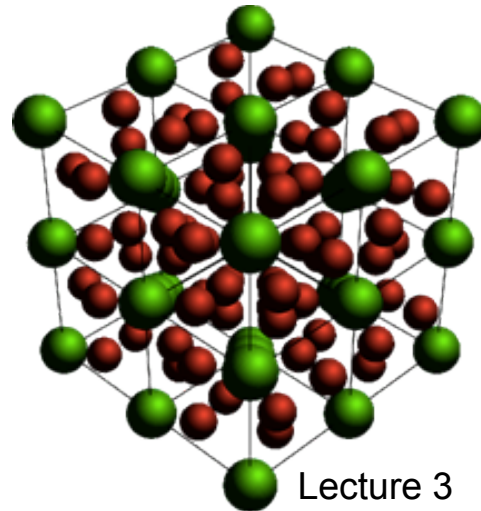
Stage II: Multifilamentary
composite

Stage III: Twisting and spooling

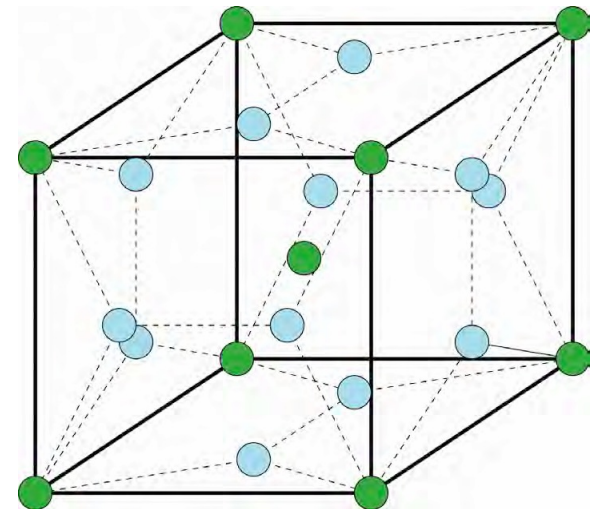
Nb₃Sn: the 1st “high field” conductor

- Nb₃Sn is an intermetallic compound with an “A15” structure
- A brittle composite that cannot be drawn after formation
- T_C & H_{C2} depend on Sn content: optimal is 20-25 weight%
- J_c depends on the microstructure (grain structure)
- Cost < \$10/kA·m
- A number of processes have been developed for wires
- Nb (6/cube) Sn (2/cube): Nb₃Sn

Sn on BCC lattice
Nb on orthogonal
chains across faces



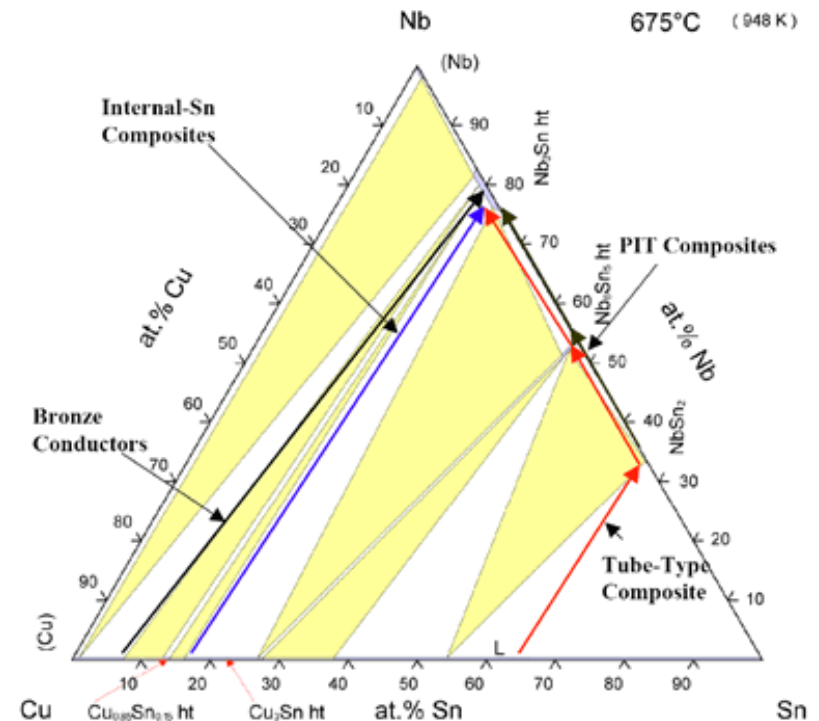
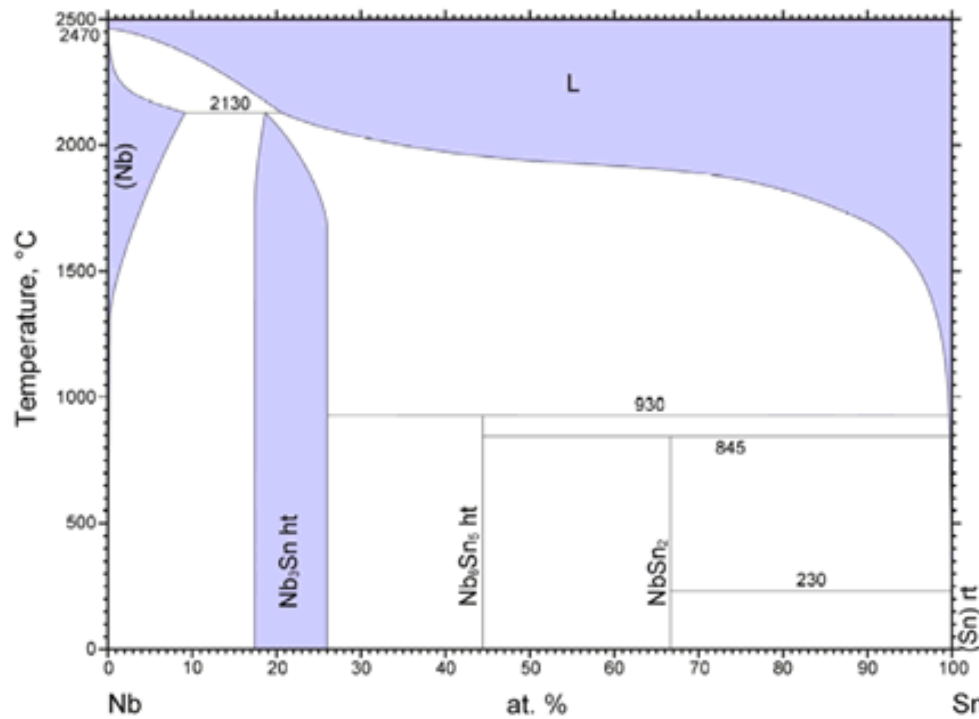
Lecture 3



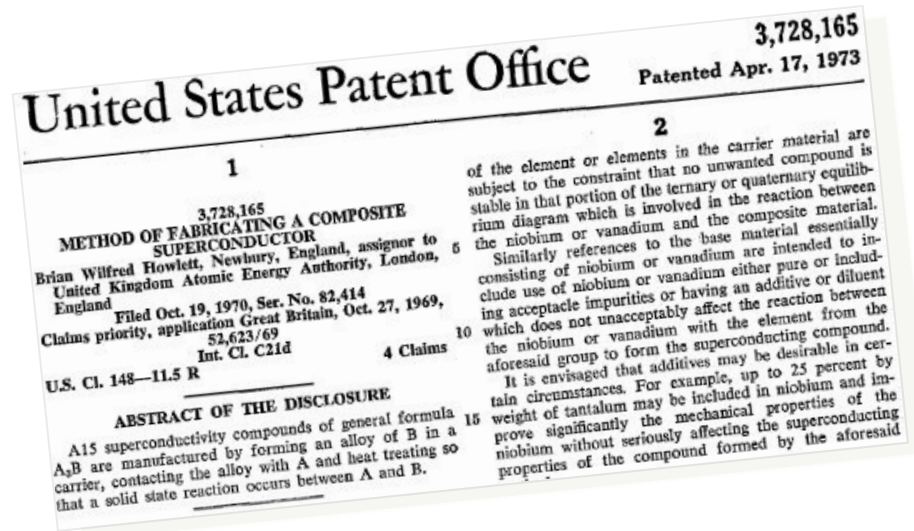
15

Nb₃Sn phase diagram – more complex than NbTi

- Reacting at 925 °C to 1050 °C was typically required to form Nb₃Sn from Nb and Sn – making it difficult to apply to the fabrication of multifilamentary strand.



Breakthrough . . . the Bronze Process ... wires

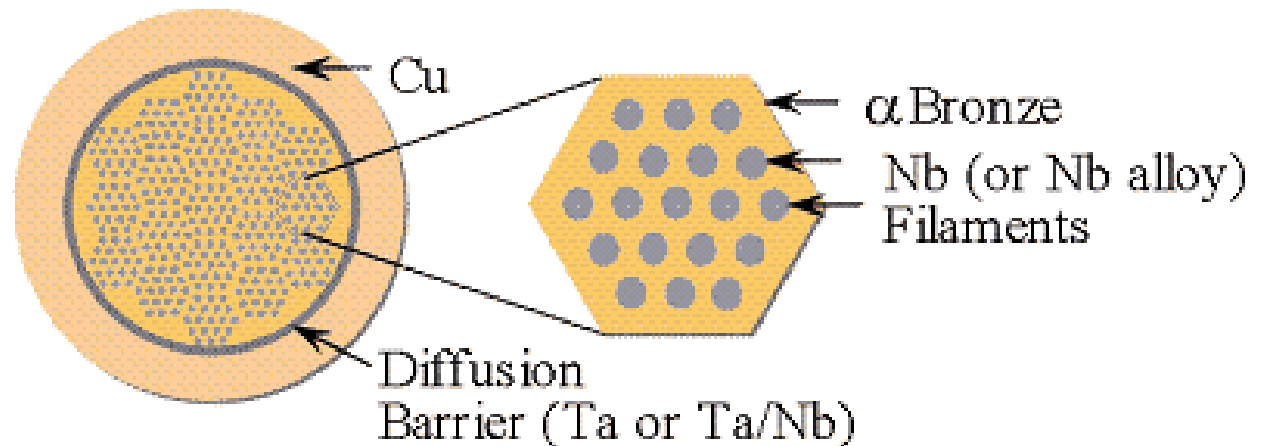


A15 compound layers (Nb_3Sn and V_3Ga) could be formed at the interface of Nb(V) and Cu-Sn(Ga) [bronze] without forming undesirable compounds *and* at less elevated temperatures, e. g., 700 °C, from composites of Nb(or V) and bronze mechanically co-reduced in size.

- Breakthrough made simultaneously by three groups '69-70:
- K. Tachikawa at the National Research Institute for Metals in Japan
- A. R. Kaufman at the Whittaker Corporation in the USA
- E. W. Howlett at the Atomic Energy Research Establishment at Harwell in Great Britain

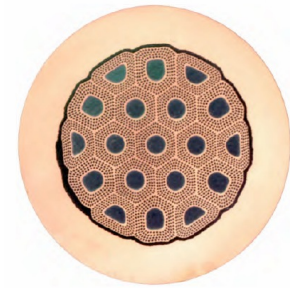
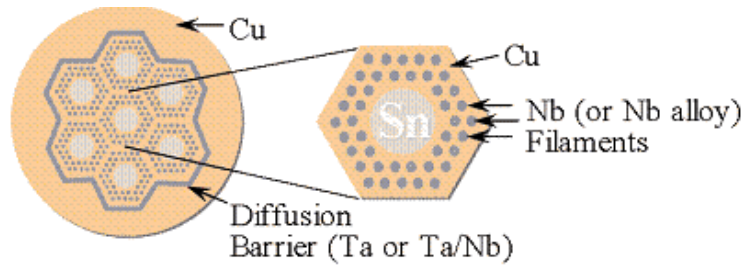
Bronze Process – historical breakthrough for wires

- Start with Nb filaments in a bronze matrix
- Diffusion of Sn into Nb
- Typical parameters: 700°C, 1-10 days (max. diff. 5-10 μm)
- Cu: prevents Nb_6Sn_5 from forming; a catalyst
- Temperature: good stoichiometry vs. small grains
- Bronze: 16wt.%Sn max.; >13% makes drawing difficult
- Maximum Nb_3Sn : ~25wt.%
- Small filament size

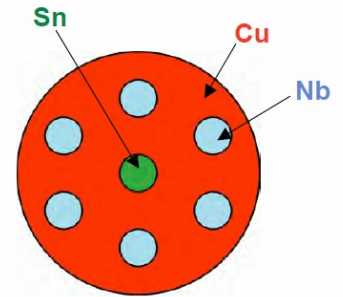
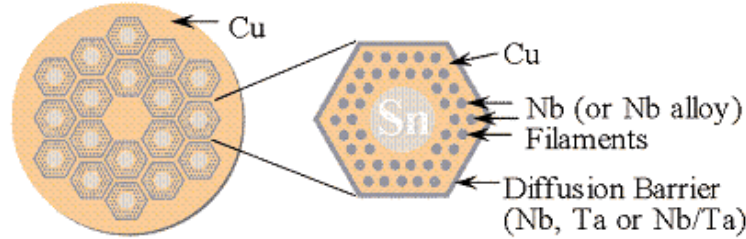


Internal Tin

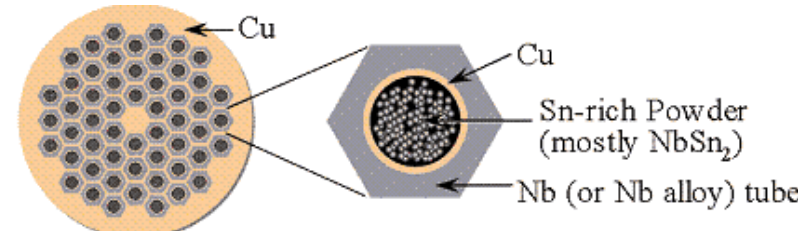
Internal Sn
(Single
Barrier)



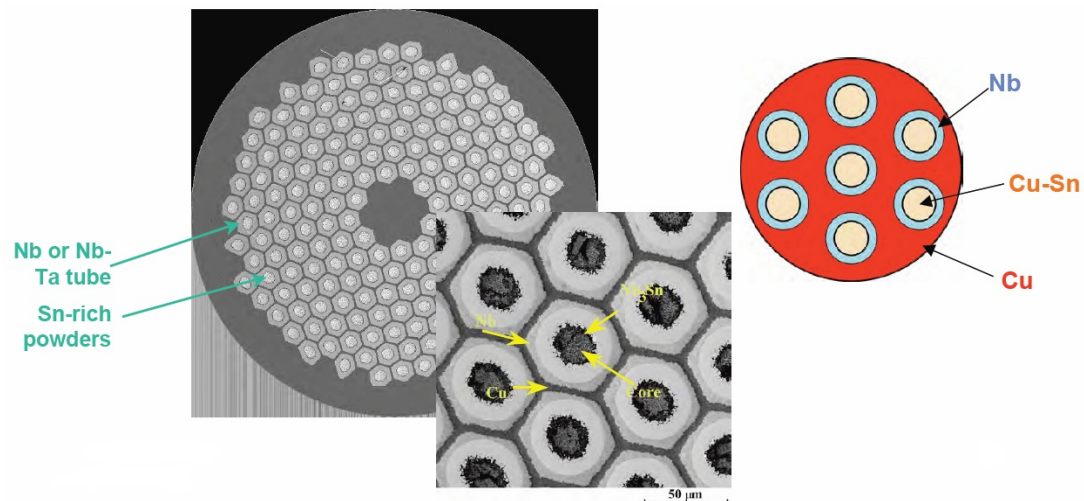
Internal Sn
(Distributed
Barrier)



Powder in
Tube (PIT)



Powder-in-tube



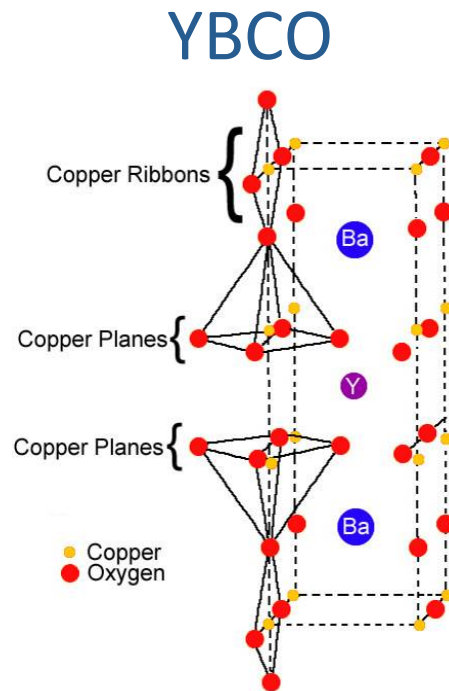
HTS v Nb₃Sn for large, high field magnets

- ☉ Conductor $J_c(B,T)$, n-value, homogeneity
- ☉ Conductor I_c - strain
- ☉ Conductor scale-up
- ☉ Packaging (insulation & reinforcement)
- ☉ Coil manufacturing
- ☉ Stability, quench detection, quench protection
- ☉ Application specific issues field profile, homogeneity, heat & radiation resistance
- ☉ Overall materials complexity
- ☉ Costs; systems pull not firmly established
- ☉ Bi2212 & YBCO have conductor-specific challenges

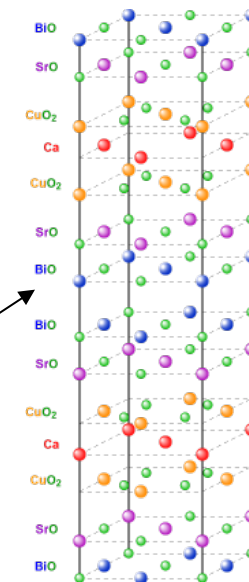
HTS is enabling technology, not replacement technology

HTS crystal structures – anisotropy dominates

- Each has highly anisotropic electro-magnetic behavior



Bi2212

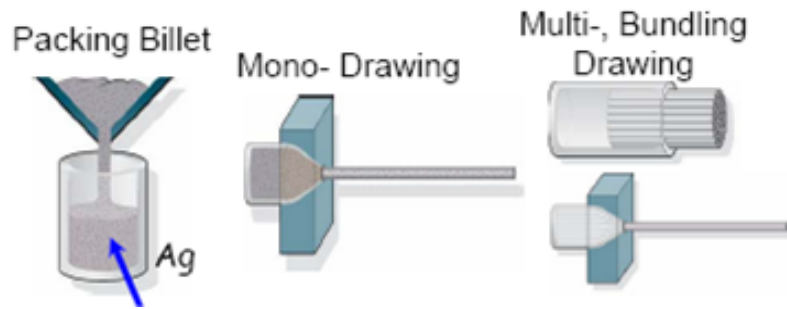


Micaceous double BiO layers; great for deformation

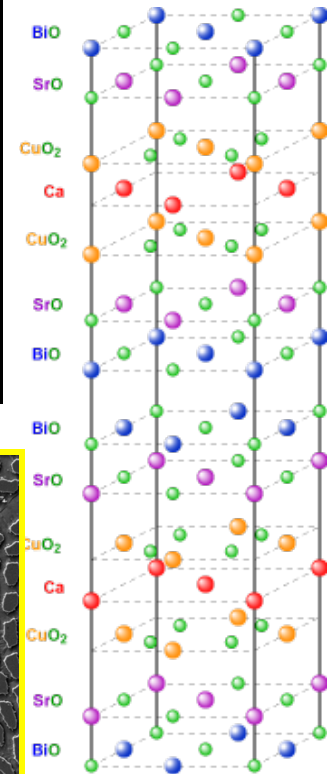
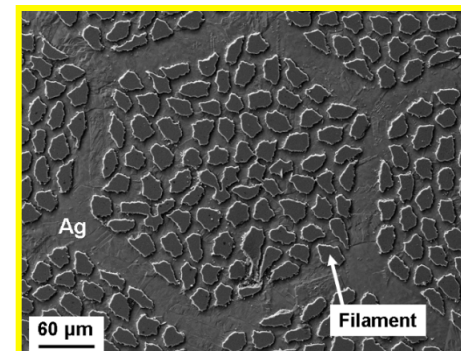
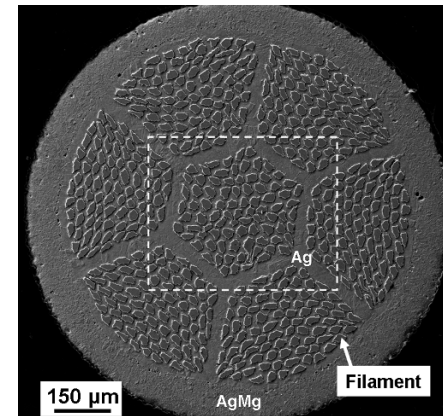
Bi-axial texture required for transport
Not AS anisotropic as Bi2212
(relatively) good flux pinning

c-axis texture required
VERY anisotropic
very weak flux pinning

Emerging conductor: $\text{Bi}_2\text{Sr}_2\text{CaCu}_2\text{O}_x$



- ☐ Formed by powder-in-tube process
- ☐ Requires Ag/AgX matrix
- ☐ Only HTS round wire option
- ☐ Only HTS conductor w/isotropic EM behavior, despite crystalline anisotropy



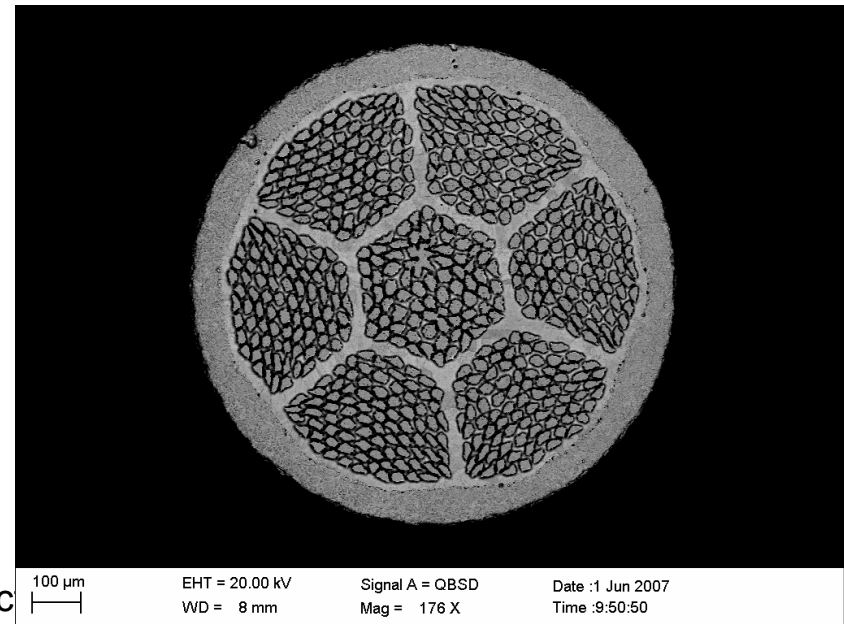
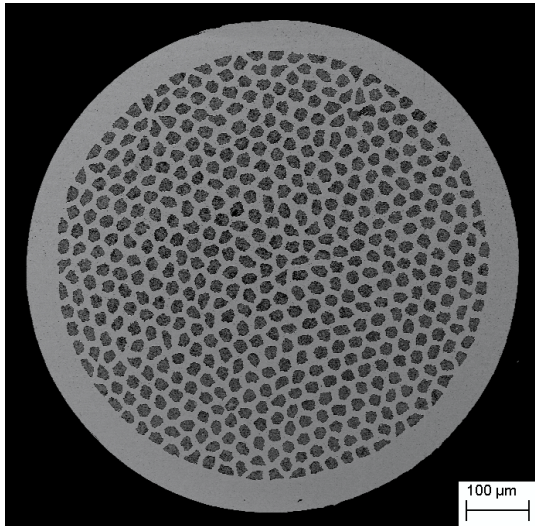
If Bi2212 wasn't the only material capable of generating >25 T in a round wire, one would never try to develop it

Bi2212 dogma ... or why it is the way it is

- To form a multifilamentary wire, a ductile matrix is required
 - Powder-in-tube
- For grain-to-grain connectivity in a wire, the powder/grains must be well-bonded via heat treatment after wire-drawing
 - Connectivity only results if significant liquid phase is created during the heat treatment (due to small coherence length)
 - Bi2212 melts incongruently through a peritectic reaction
 - Solid (Bi2212) \rightarrow liquid + solid (neither of which are Bi2212)
- Oxygen content in Bi2212 evolves during heat treatment and is important for final properties
 - Matrix must allow oxygen diffusion, not oxidize, and be chemically compatible with Bi2212
 - Therefore Ag is used \rightarrow very limiting (and mechanically weak)
 - Ag used next to filaments, AgMg for “outer sheath”

Bi2212 challenges & the partial-melt process

- To date, “partial-melt process” and its variants are that standard heat-treatments for Bi2212 wire
 - like Churchill’s description of democracy – it’s the worst possible option except for all of the others
- And while we now (somewhat) understand why it works, it is still rather surprising
- We start with:

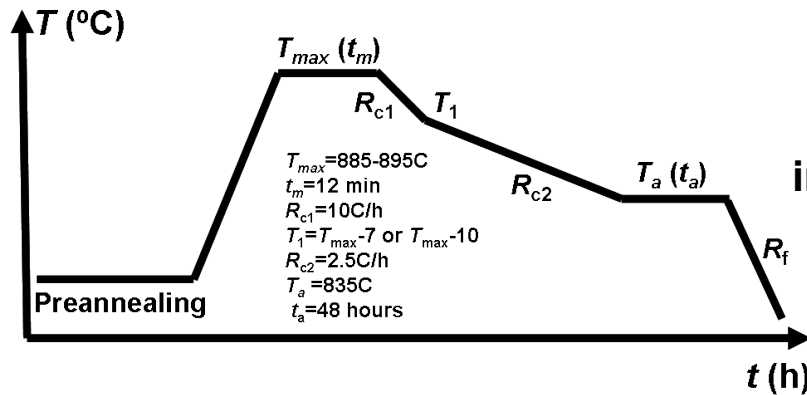


Lec

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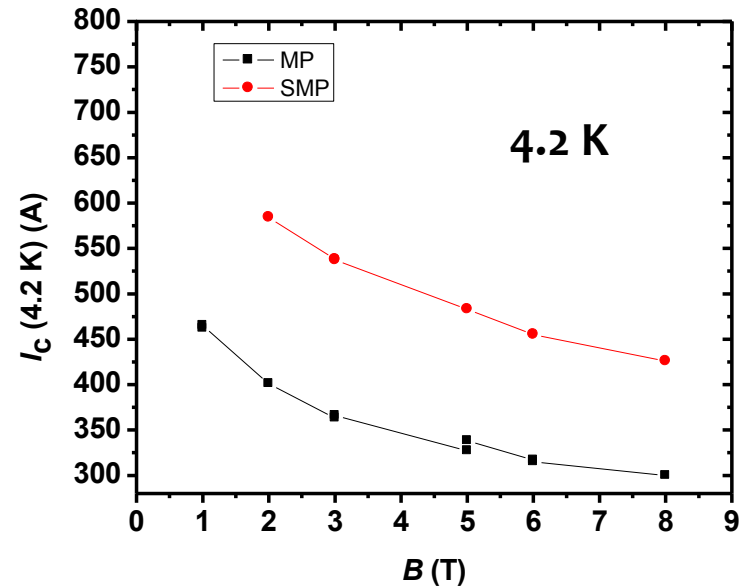
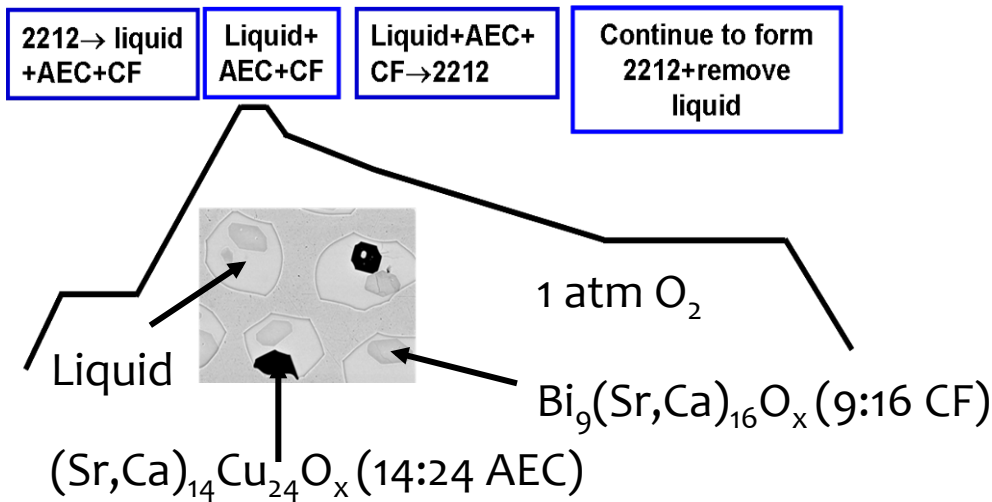
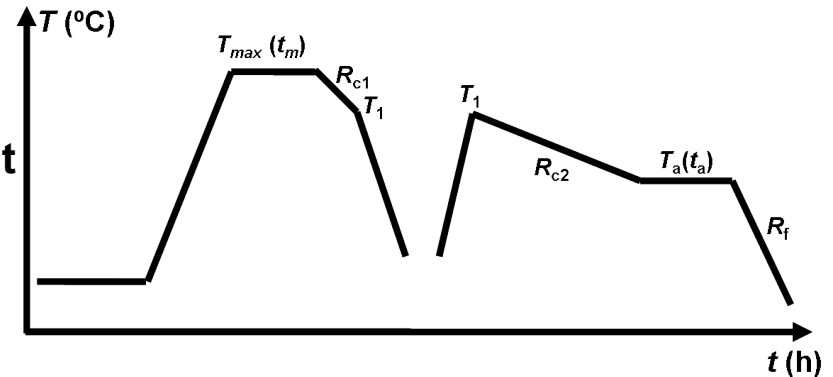
We process above the peritectic melt

Standard partial-melt processing (PMP)

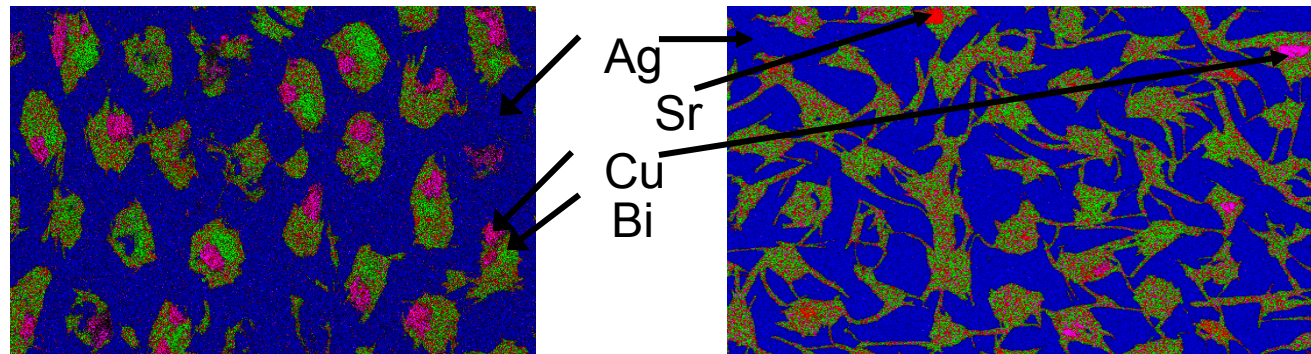


30-40% improvement

Split melt processing (SMP)



and we end up with ... a complicated, inhomogeneous microstructure



$I_c \sim 0$

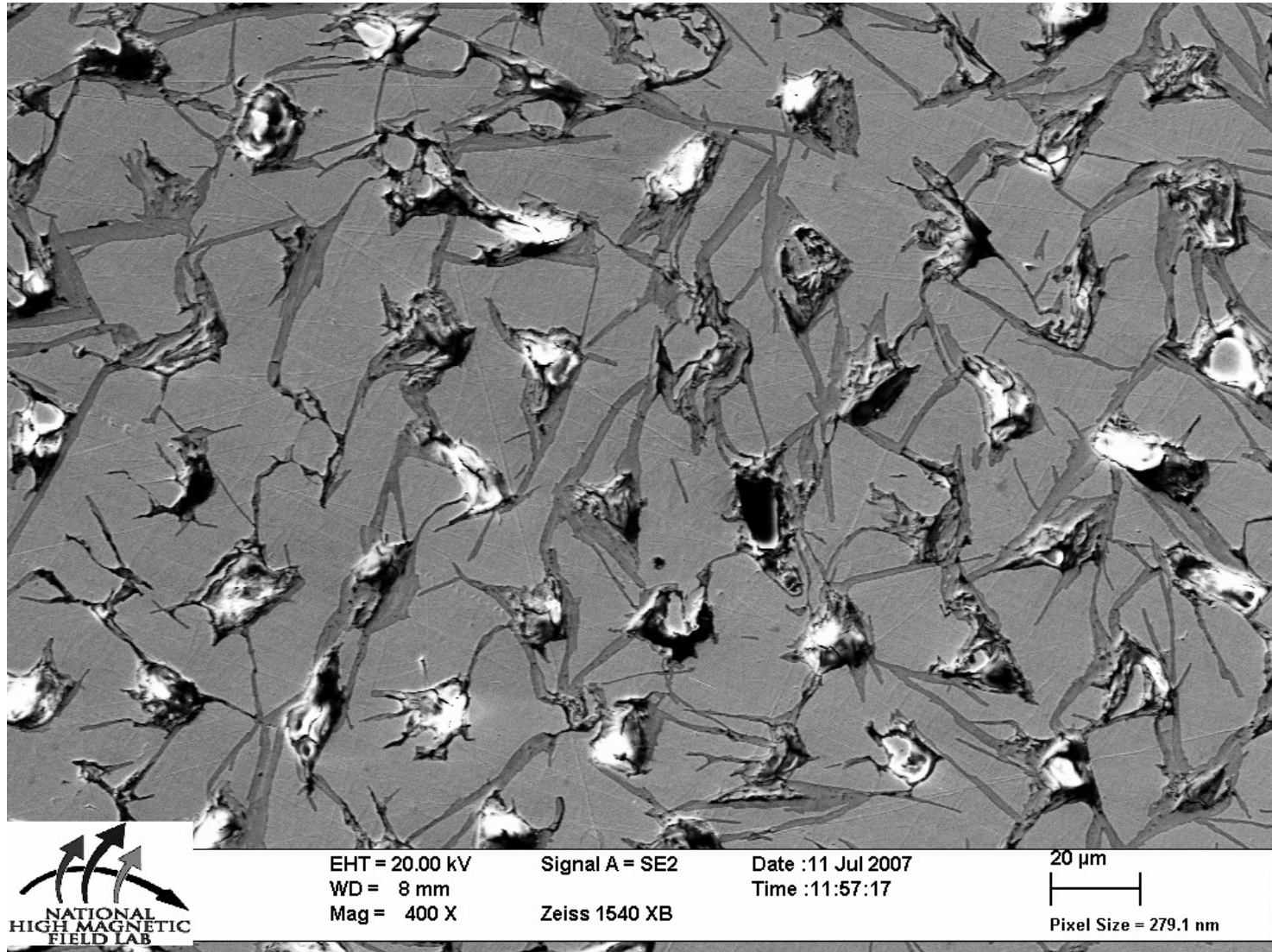
Second phases segregate in center (Bi2212 @ Ag interface);
No filament bridging

$I_c \sim 2 \text{ kA/mm}^2$

More uniform chemistry
Significant bridging



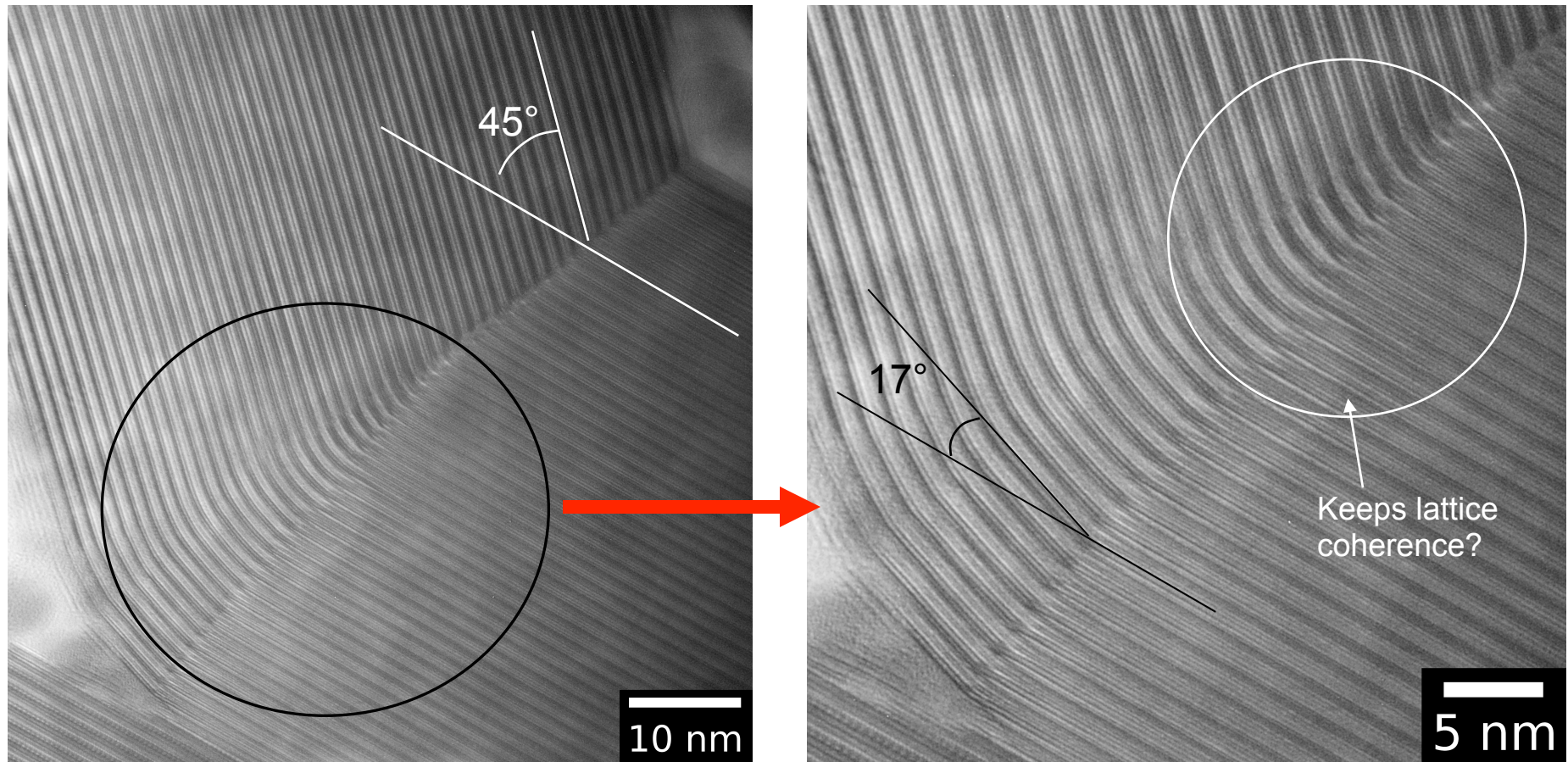
Bi2212 microstructure



Why does it carry current?

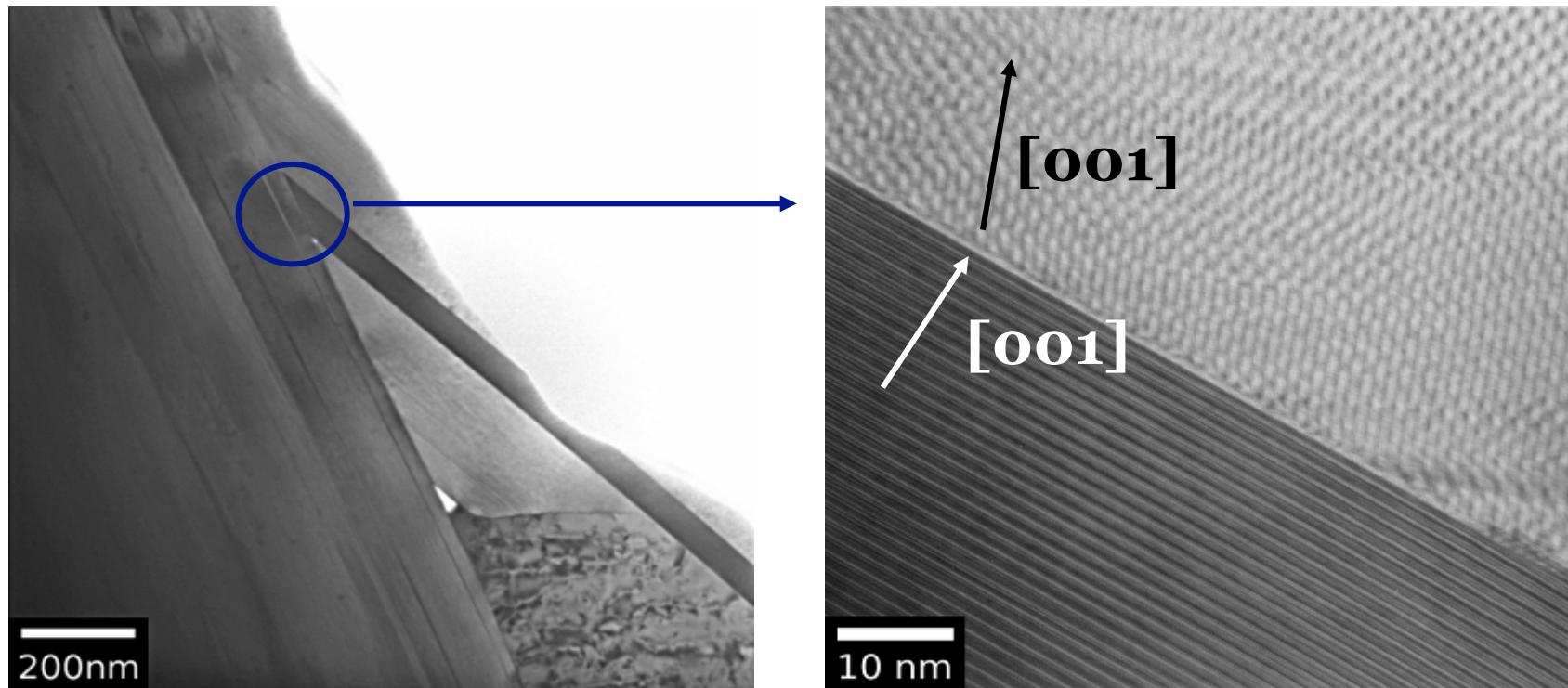
- ☐ How does microstructure evolve to produce high J_c ?
- ☐ Why is there high J_c with poor texture?
- ☐ Do the interfilamentary bridges play a key role in transport?
- ☐ Which bridges? ... microstructure is a statistical mess!
- ☐ What about the significant porosity that remains?
- ☐ Let's look at different length scales

Bi2212 lattice planes change direction



- The tilt angle between two grains is 45°
- Lattice planes bend to connect to the adjacent grain, reducing the tilt angle to 17°

Transverse TEM of “small” bridge

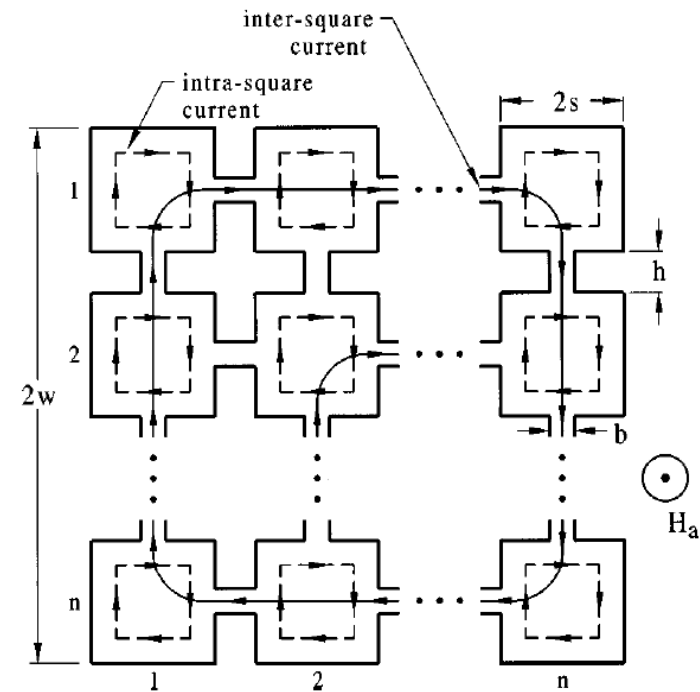


- 🔍 Images of a junction of an outgrowth (bridge) and a filament
- 🔍 Misorientation (not pure tilt) angle $\sim 23^\circ$
- 🔍 Grain boundary is clean but *should not* support transport ... but does it?

F. Kametani

“Connectivity” and the role of bridges

- Grain flexibility overcomes lack of texture
- For connectivity, consider two-dimensional treatment based upon YBCO thin film grain-to-grain connectivity
- Bi2212 case is 3D, highly inhomogeneous extension
- Macroscopic approach?

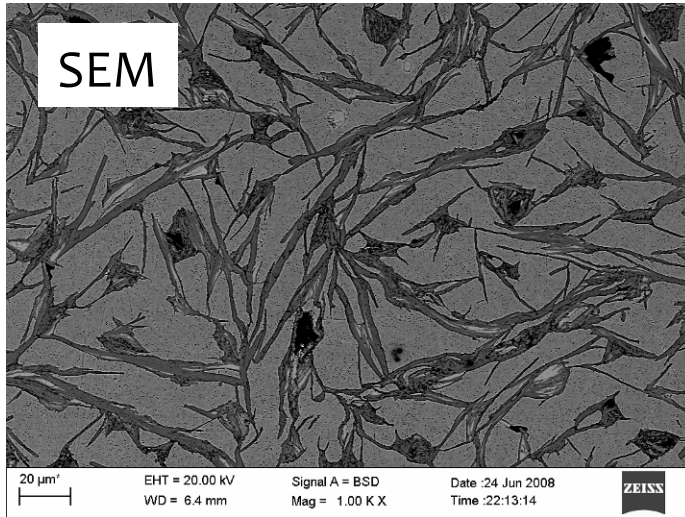


$$C = \frac{b}{2s + h} \quad J_c^I = \frac{b}{2s + h} J_c$$

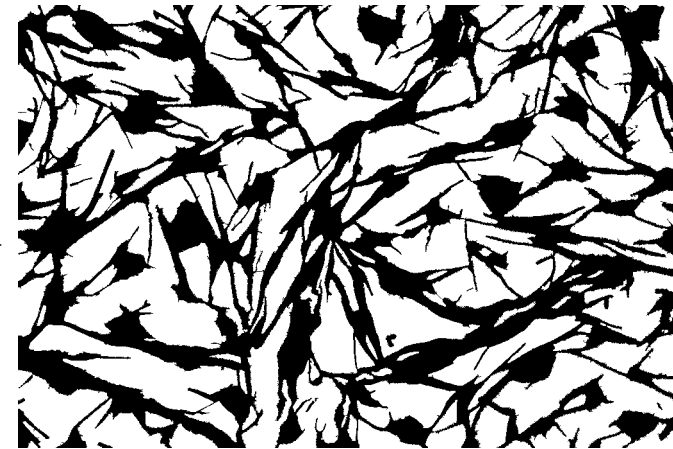
Muller, Andrikidis, Du, Leslie and Foley, PRB **60**(1) 1999 659

Develop quantitative image analysis

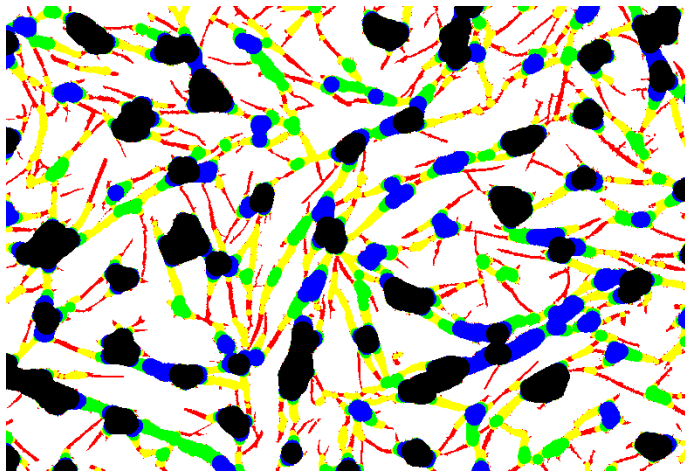
Do bridges correlate with properties?



Photoshop
+ Image J

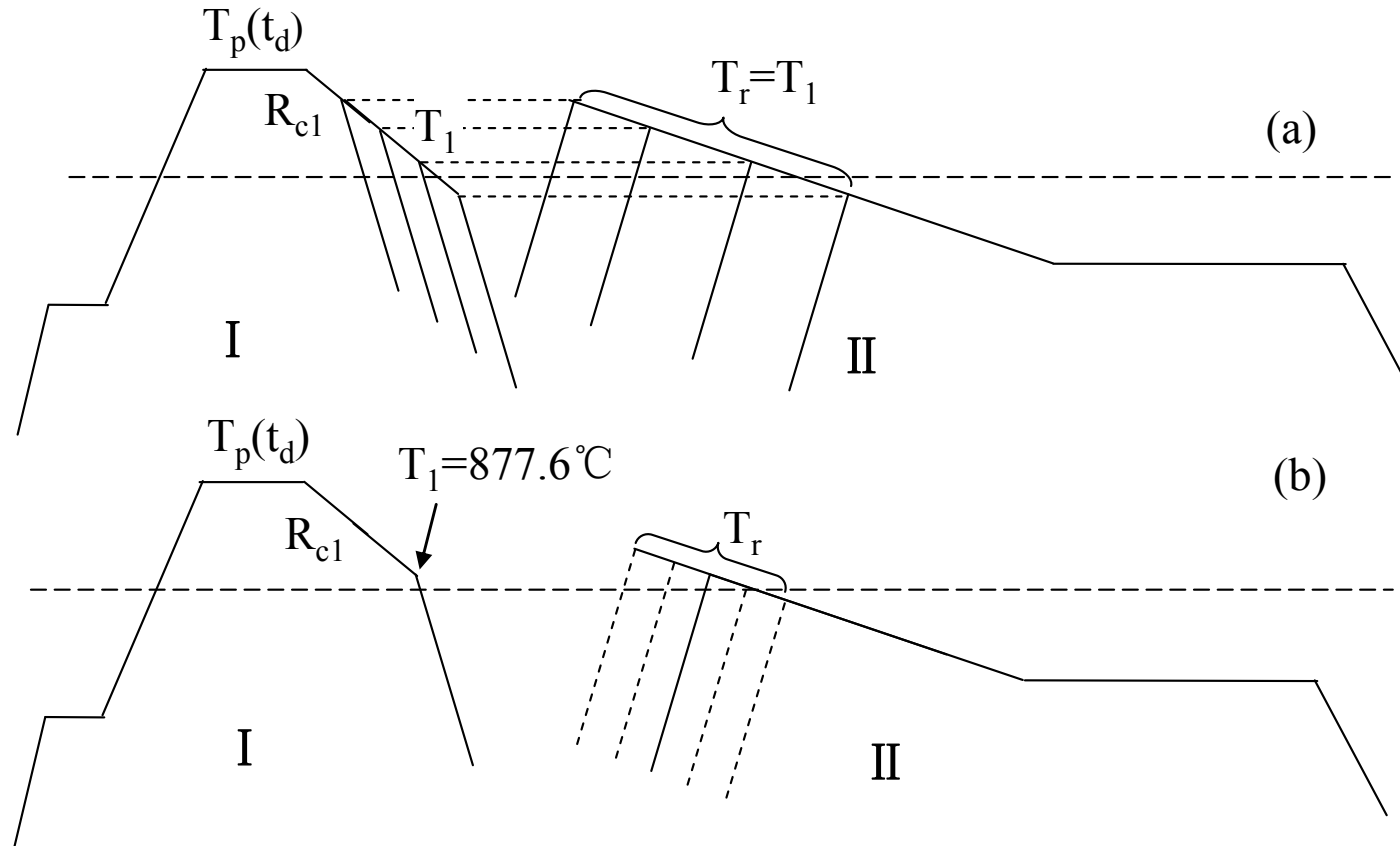


Matlab

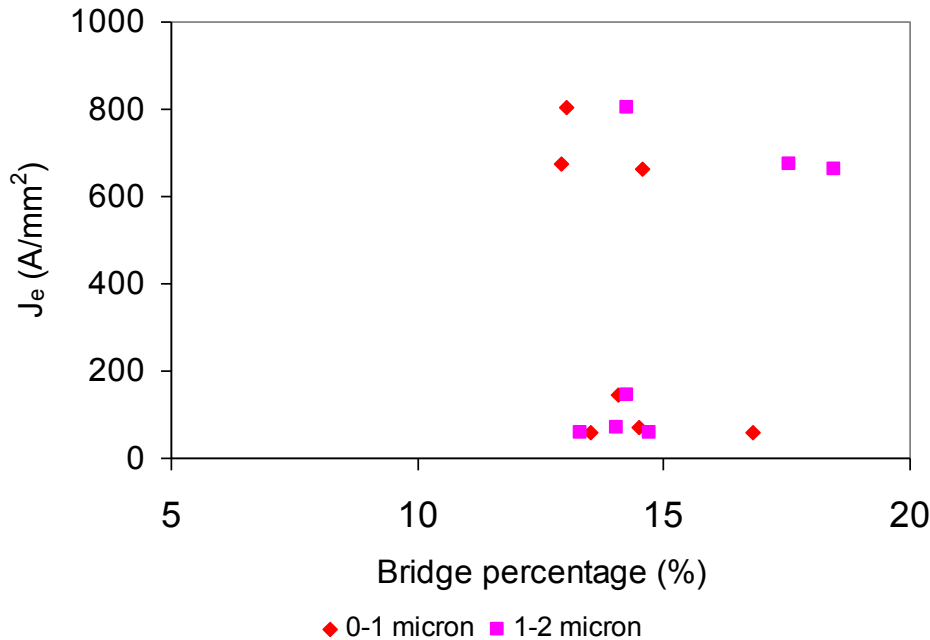


- | | |
|-----------------|----------------------|
| Ag-alloy | White, all |
| Oxide filaments | Black > 4 μm |
| Oxide bridges | 4 μm > Blue > 3 μm |
| Oxide bridges | 3 μm > Green > 2 μm |
| Oxide bridges | 2 μm > Yellow > 1 μm |
| Oxide bridges | Red < 1 μm |

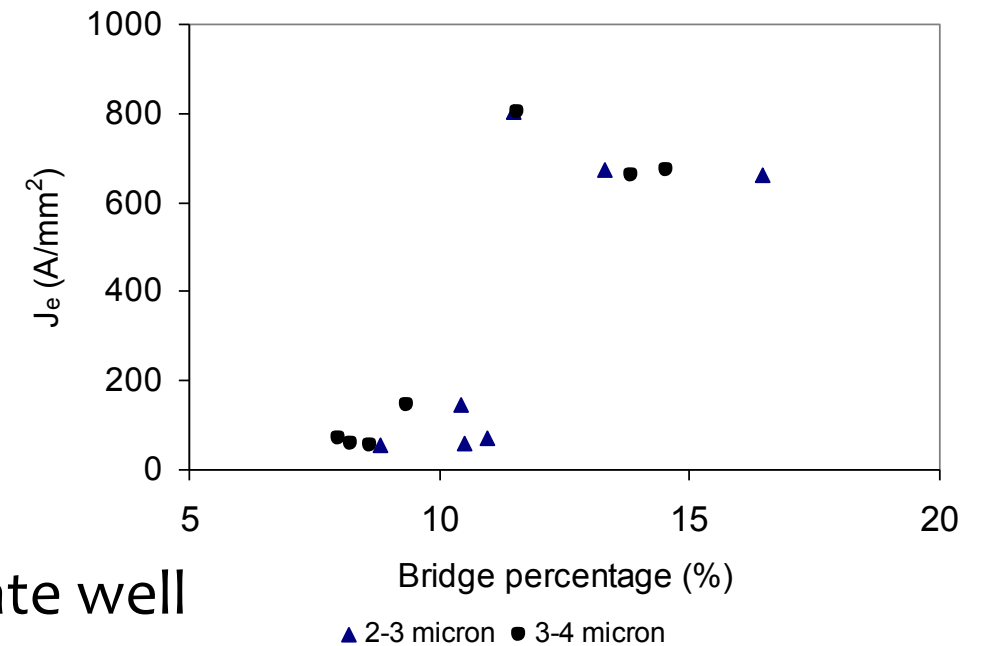
Vary the processing, vary the microstructure



Do bridges correlate with J_c ?

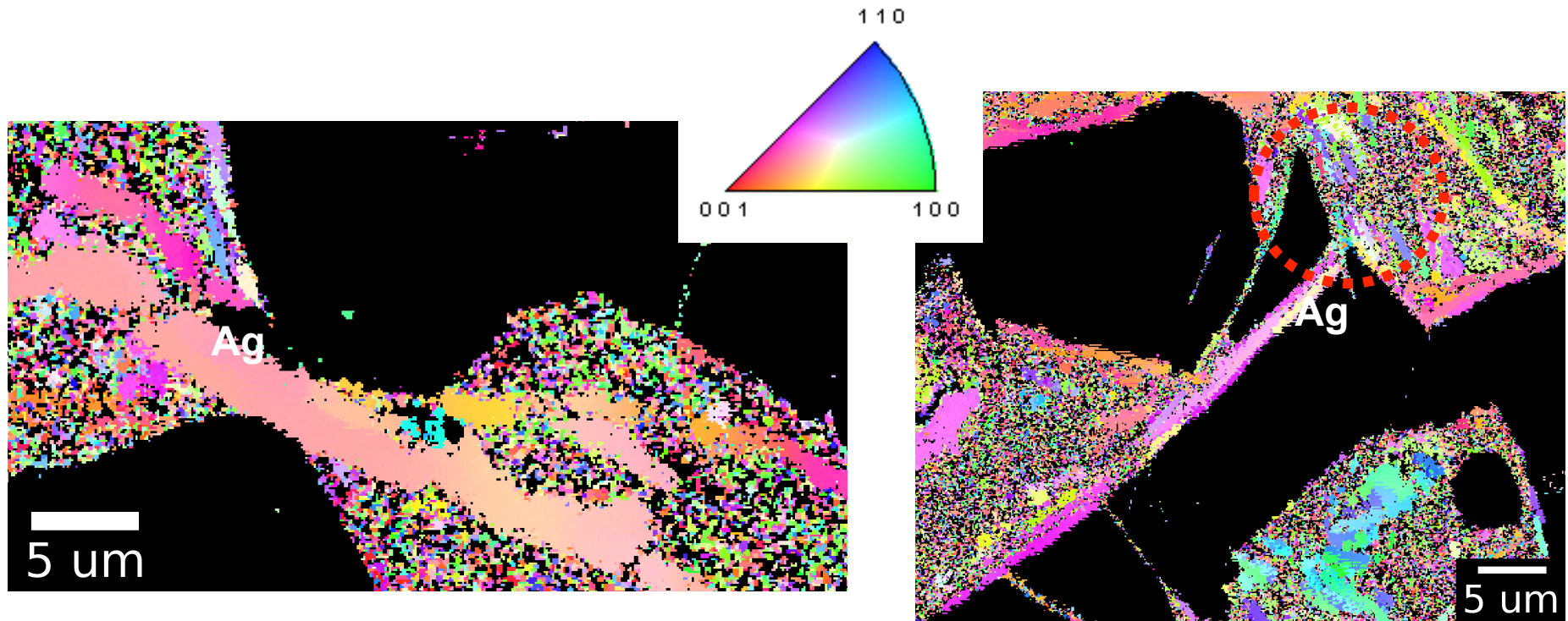


1-2 μm bridges do not correlate



2-4 μm bridges correlate well

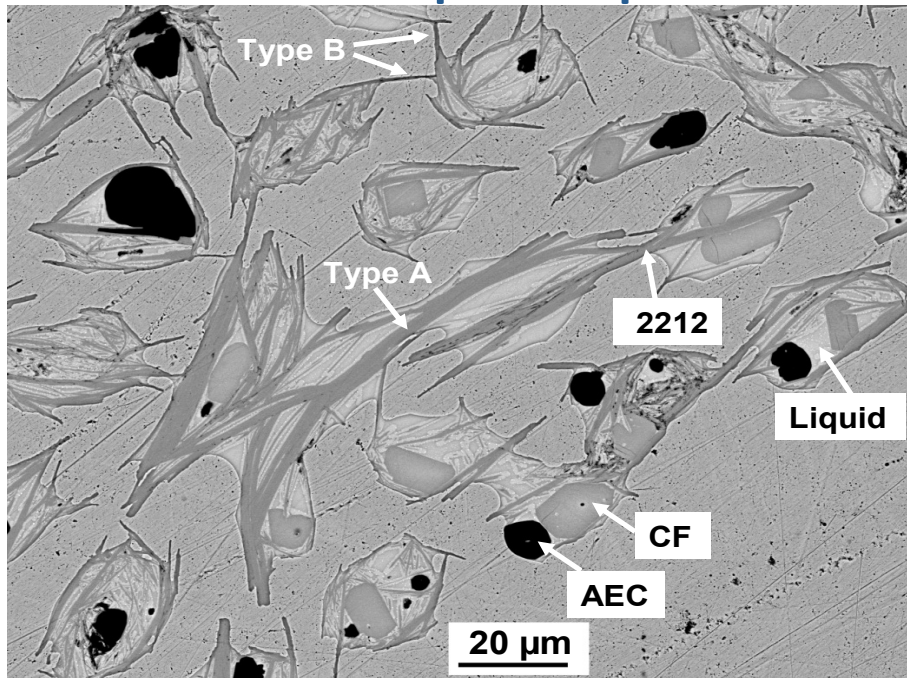
Grain orientation mapping agrees!



- LAGBs in some bridges; current can cross the bridge to the adjacent grain
- HAGBs are more typical than LAGBs in bridges; minimal current flow

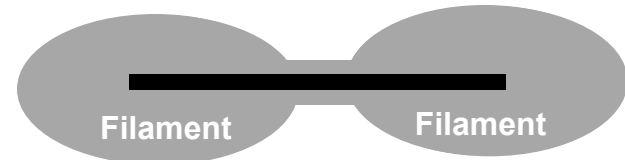
Why are there two types of bridges?

Samples quenched as Bi2212 nucleates

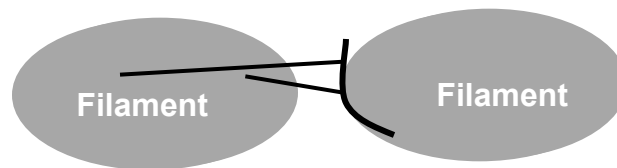


- Type-A bridges
 - Large, thick single Bi2212 grain/colony
 - Supercurrent crosses type-A bridges from one filament to another

Filament-filament bonding

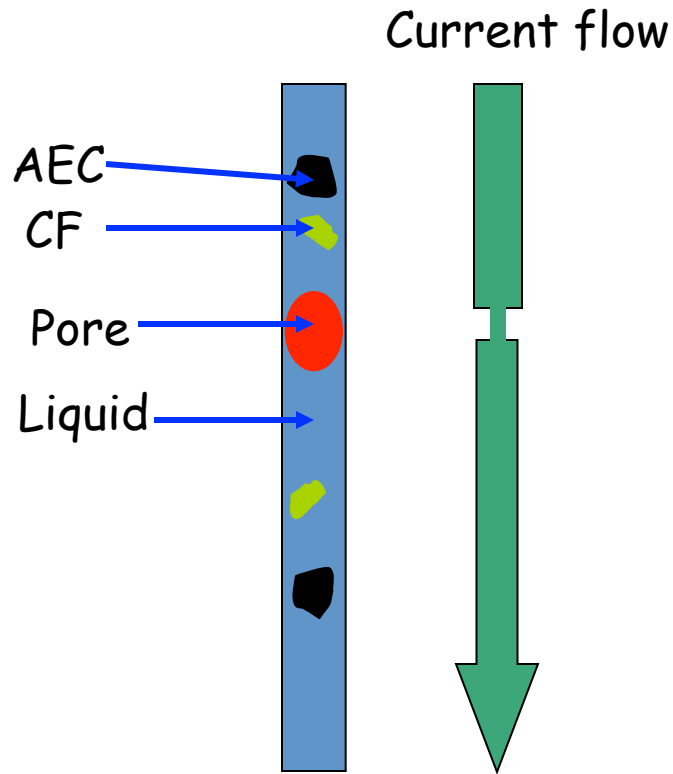


Isolated filaments

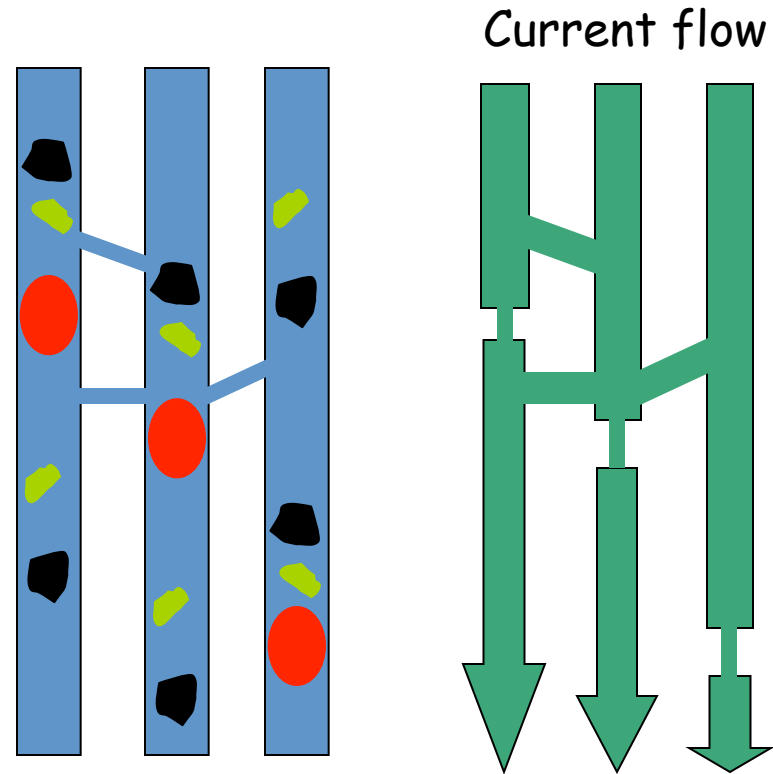


- Type-B bridges
 - Result from Bi2212 outgrowths
 - High angle grain boundaries
 - Low transport

Interconnected 3-D current flow path ... “walking in Venice” or “drunken electrons”



Monocore 2212



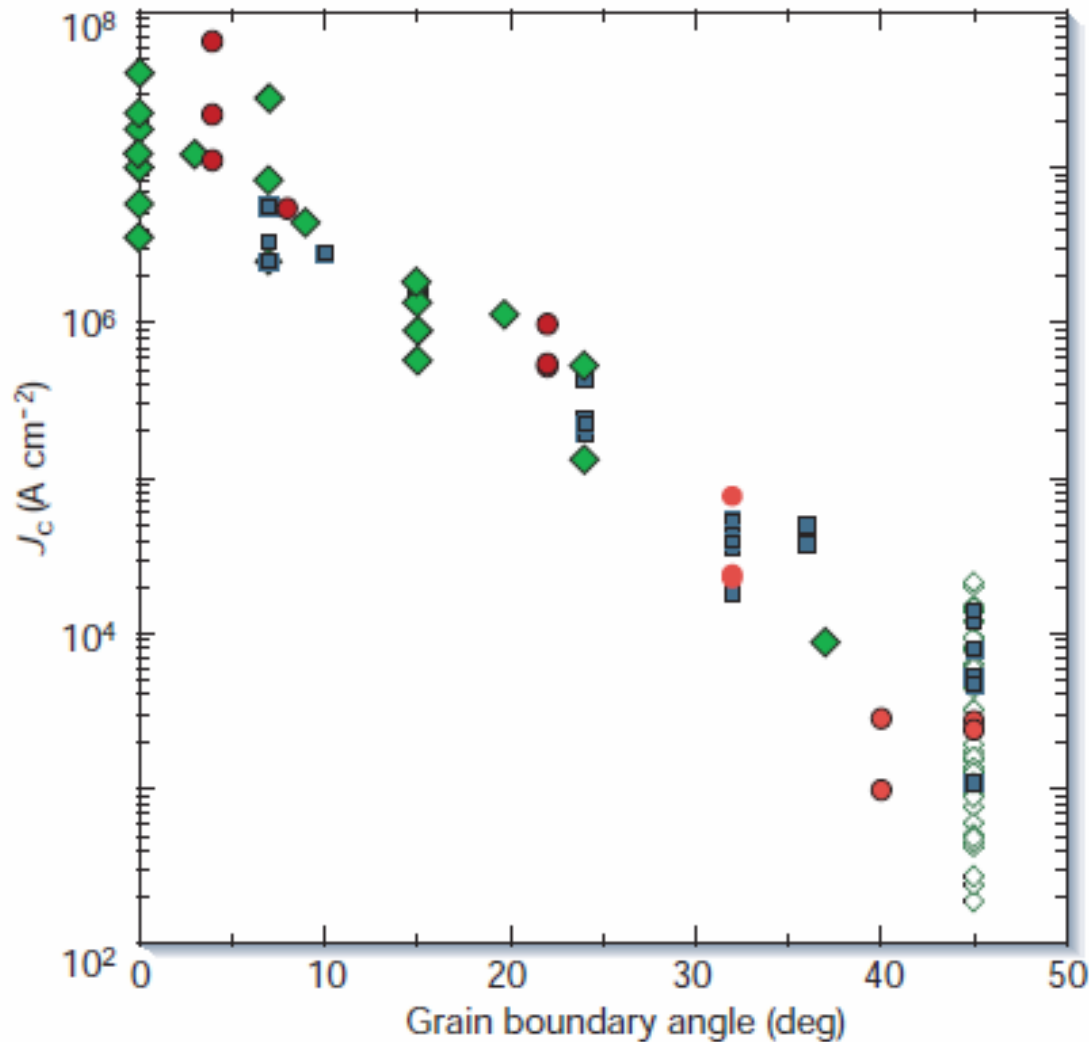
Interconnected Bi2212 filaments

So can Bi2112 improve significantly?

- ☐ Remarkable that Bi2212 microstructure carries high transport current
- ☐ Two primary obstacles to improvements (or, if you're an optimist – why it can get a lot better)
 - ☐ Porosity is significant; removing porosity in short samples shows significant increase in J_c
 - ☐ Reconversion to Bi2212 “nucleation site saturation limited” (split-melt processing shows that additional nucleation sites can be formed)
- ☐ Other unexplored opportunities
 - ☐ Varying Bi2212 composition ... so many variables!

YBCO coated conductors & Dimos experiment

- Transport across a grain boundary in a bi-crystal



Weak-linked YBCO ... the need for bi-axial texture

- J_b across the grain boundary drops exponentially below that of the grains, $J_b = J_0 \exp(-\theta/\theta_c)$, as a function of the misorientation angle θ , where $\theta_c \sim 2-5^\circ$
- This extreme sensitivity to misorientation, coupled with the intrinsic anisotropy, demands bi-axial texture in YBCO to minimize grain-boundary misorientation
- The “weak-link” behavior of grain boundaries is in effect a combination of this anisotropy and small coherence length

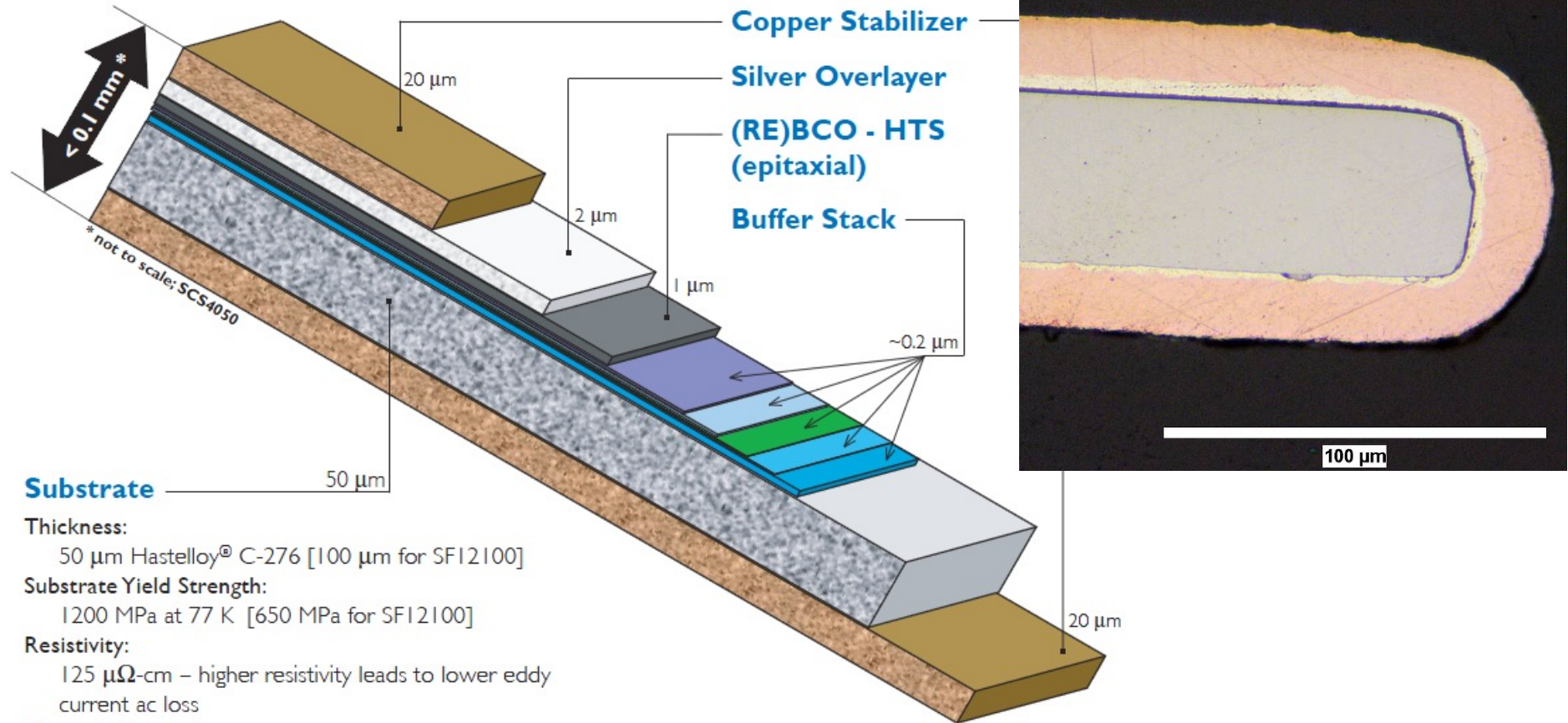
Emerging conductor: (RE)BCO coated conductor

- **ANY** method of making a conductor requires biaxial texturing; three approaches have emerged
- Rolling Assisted Bi-axial Textured Substrates (RABiTS)
 - Textured metallic substrate (NiW) serves as template
 - Requires buffer layers to separate Ni from YBCO chemically while “transmitting” texture information
- Ion Beam Assisted Deposition (IBAD)
 - Randomly oriented substrate (Hastelloy)
 - IBAD to deposit textured buffer layers which provide the template for YBCO growth
- Inclined Substrate Deposition (ISD)
 - Texture induced in buffer layers

What do (RE)BCO CCs share?

- Wide, thin tapes with very high $J_c(B)$
 - E.g., SuperPower IBAD is 12 mm wide, then slit to 4 mm
- **1-2% “fill factor” (%conductor that is superconductor)**
- Specialized buffer layers
 - Transmit/provide textured template
 - Chemical barrier between YBCO and Ni
 - Y_2O_3 , YSZ, MgO, CeO_2 , STO, are common buffer layers
- **A strong Ni-alloy substrate**
- A thin Ag cap-layer atop the (RE)BCO for environmental protection
- Cu enclosure
- Very anisotropic $J_c(B)$
- **“Engineerable” microstructure: flux pinning optimization**

SuperPower IBAD (RE)BCO



Substrate

Thickness:

50 μm Hastelloy® C-276 [100 μm for SF12100]

Substrate Yield Strength:

1200 MPa at 77 K [650 MPa for SF12100]

Resistivity:

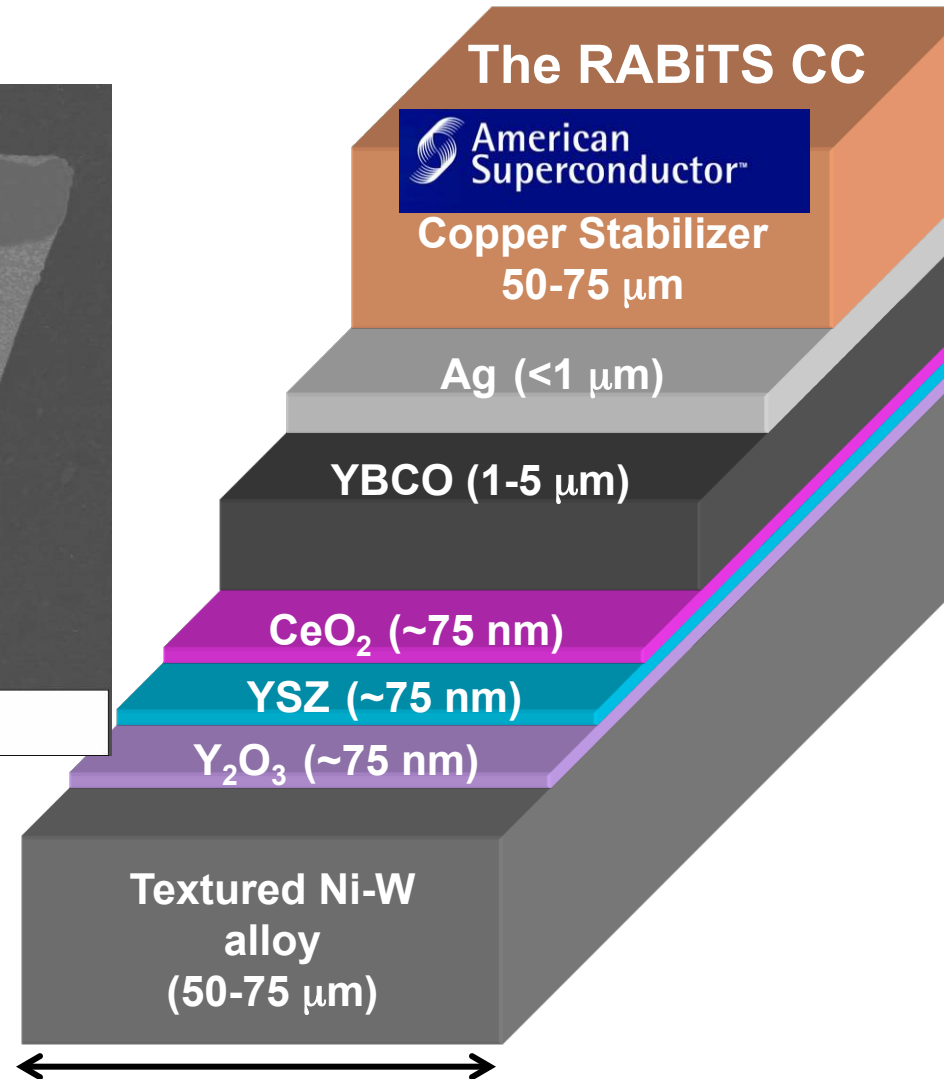
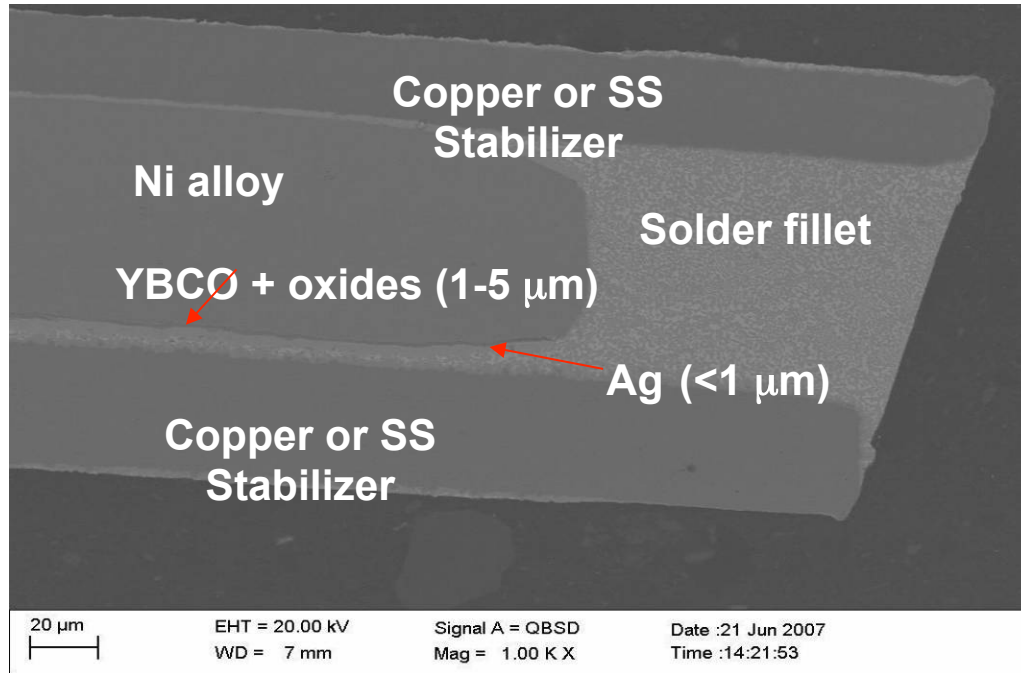
125 μΩ-cm – higher resistivity leads to lower eddy current ac loss

Magnetic Properties:

non-magnetic, leads to lower ferromagnetic ac loss

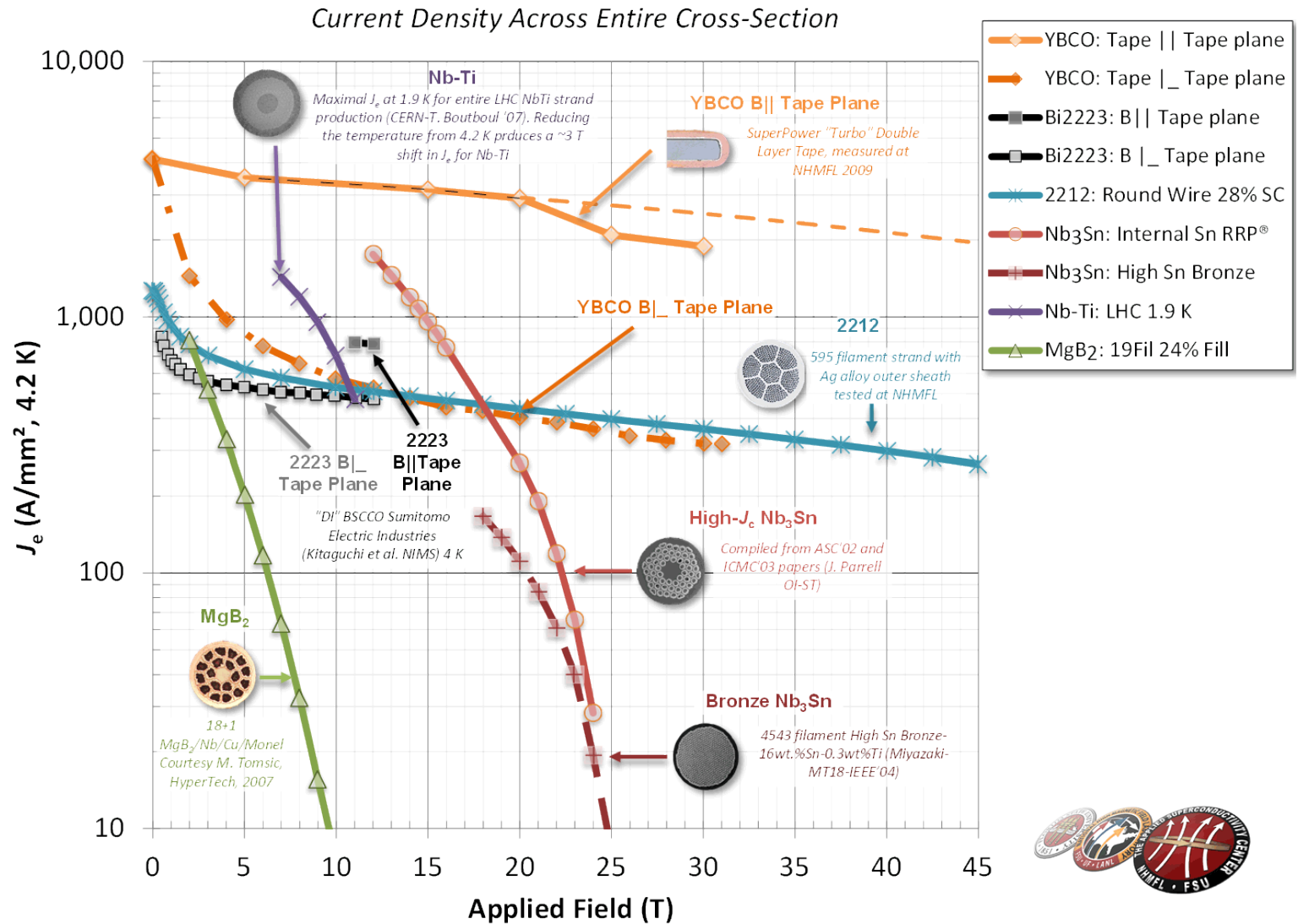
- Cu is electroplated

American Superconductor (RE)BCO Coated Conductor



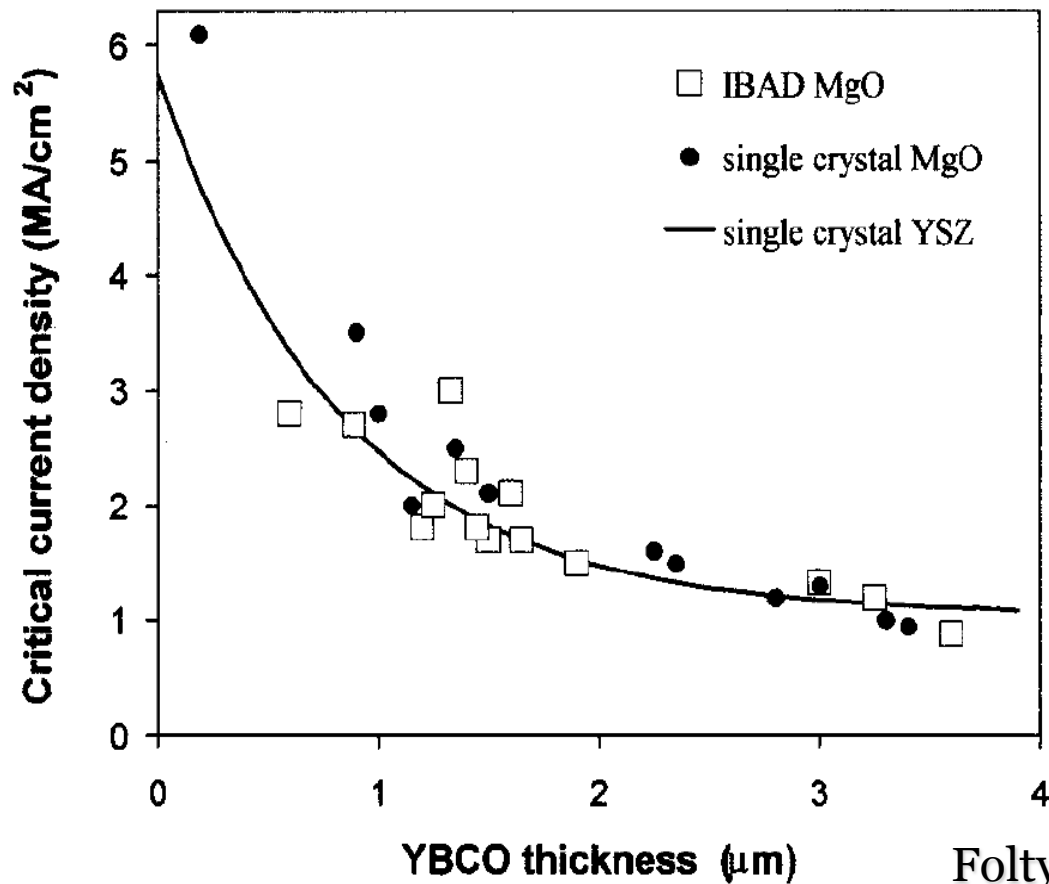
Cu is soldered – easy to use other materials, but bonding not as strong as electroplating

Recall $J_c(B)$ plot ... two YBCO curves



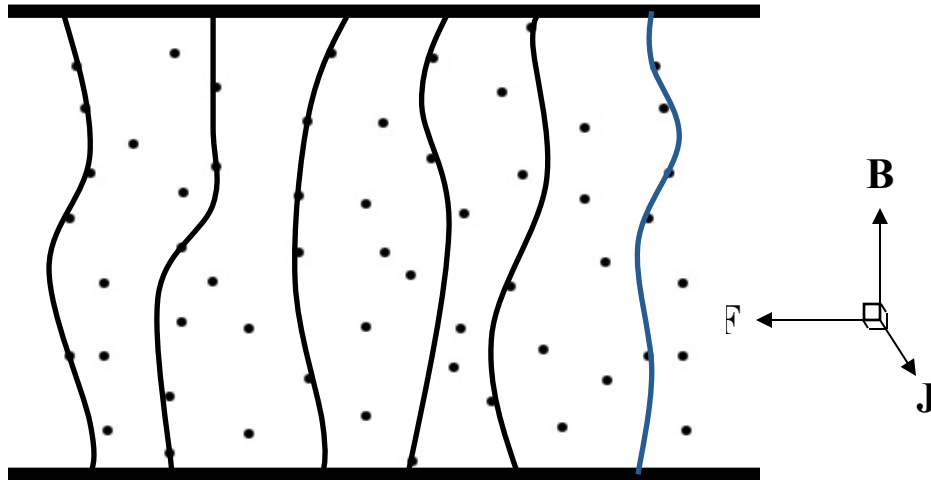
Thickness dependence of J_e

- Attempts to increase fill factor have diminishing return



Foltyn et al. APL 2003

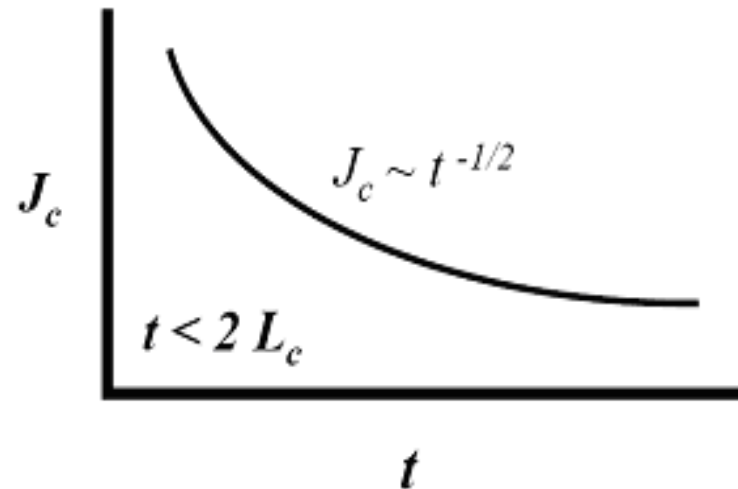
Two-dimensional flux pinning



2D Collective Pinning Theory shows that weak flux pinning & thermal fluctuations can lead to thickness dependence

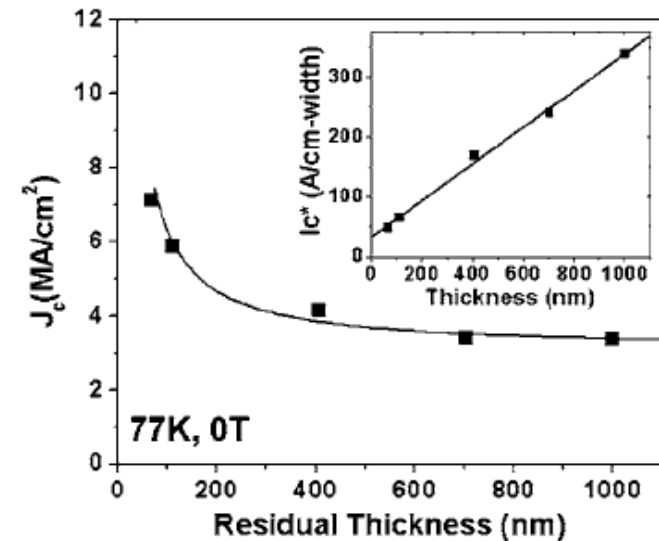
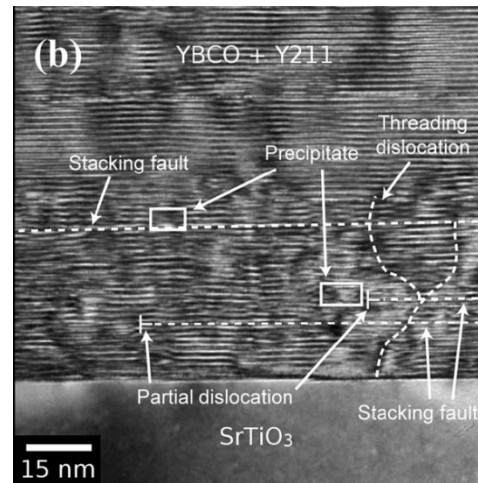
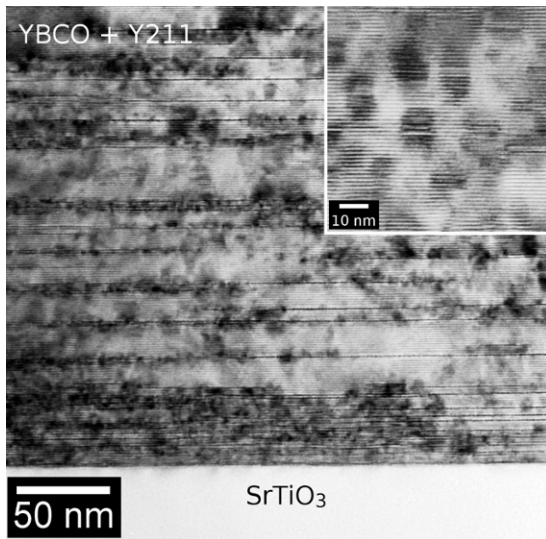
$$J_c \cong \frac{\pi^{1/2} f_p r_p}{\phi_0 d^{3/2} t^{1/2}} \approx \frac{J_d r_p \xi}{d^{3/2} t^{1/2}} \propto t^{-1/2}$$

What can be done?



Gurevich; Kim

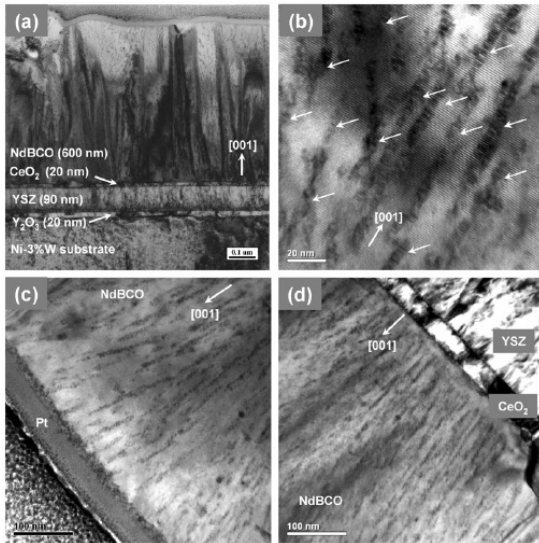
Three-dimensional flux pinning with nanoinclusions



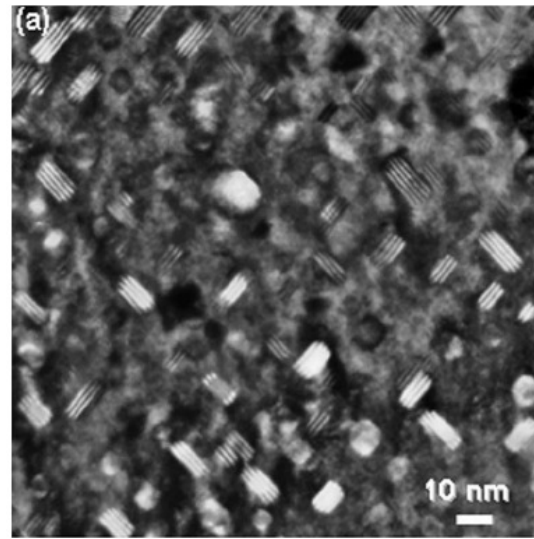
- Flux pinning inclusions reduce thickness dependence ... *but not totally*
- Multiple mechanisms in concert

Kim et al., APL 90 2007

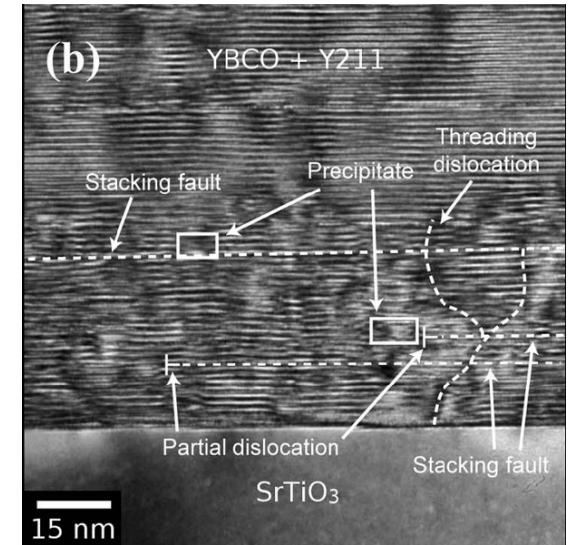
Flux pinning nano-inclusions



Columnar BaZrO₃
Wee et al., SuST 20 2007



(Y,Sm) O₃
Song et al., APL 88 2006

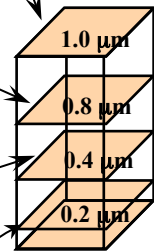
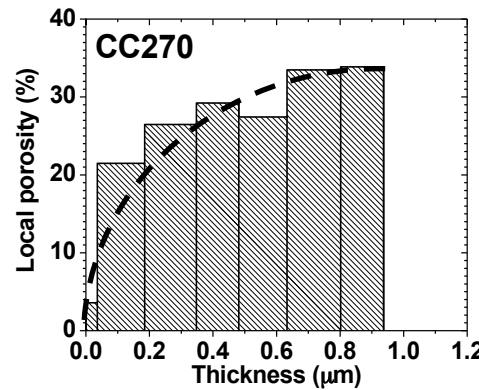
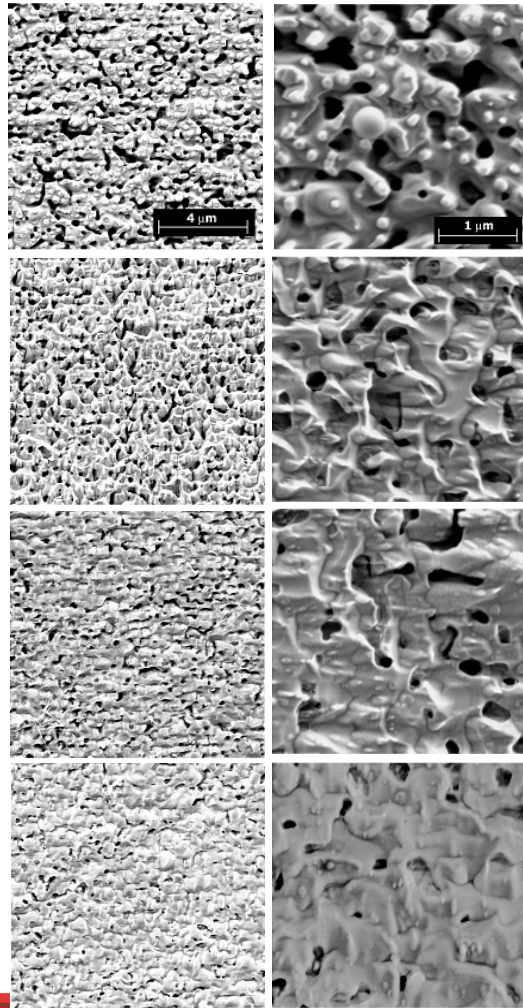


Y211
Kim et al., APL 2007

- YBCO CC chemistry facilitates wide variety of nano-inclusions for flux pinning... can high field conductor be engineered? An isotropic conductor?

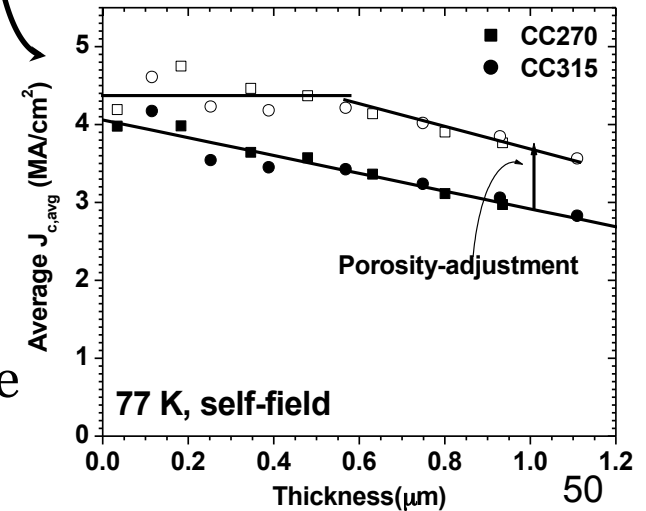
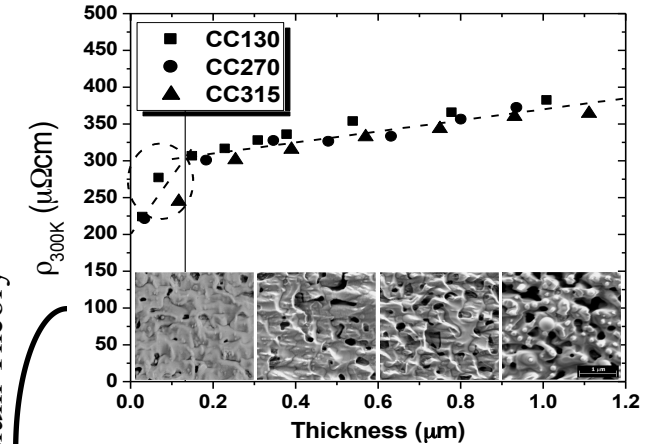
Inhomogeneous porosity

Kim, Feldmann, Gurevich, Larbalestier



Pore sizes: 50-500 nm
Can pin flux or block current depending on size

Effective Medium Theory



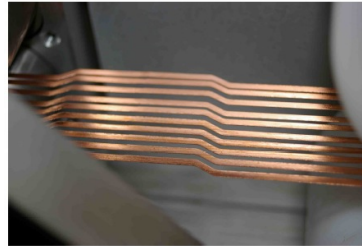
Lecture 3

Transport in YBCO CCs

- Three factors can destroy transport in YBCO CCs
 - Grain boundaries & other connectivity blockers
 - Can be improved with Ca, Nd, ... , other dopants
 - Flux pinning
 - Can be improved/engineered by plethora of nanoinclusions
 - Porosity
 - Can be improved via better processing
- Solving these simultaneously may
 - Reduce anisotropic electromagnetic behavior
 - Provide flexibility in operating current
 - Improve J_e
 - Result in a conductor that can be engineered

What about cables made from wide, thin tape?

Roebel cable



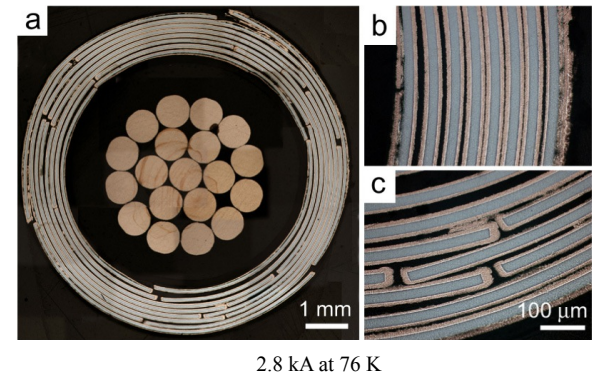
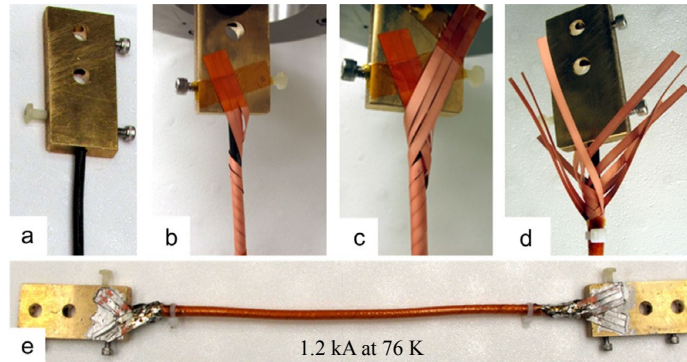
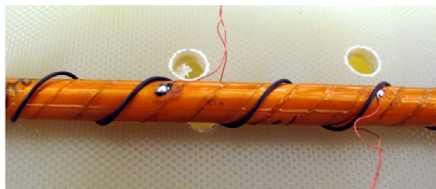
N J Long, R Badcock, P Beck, M Mulholland, N Ross, M Staines, H Sun, J Hamilton, R G Buckley, Journal of Physics: Conference Series 97 (2008) 012280

Twisted stacked tape cable



M. Takayasu et al., "Cabling Method for High Current Conductors Made of HTS Tapes", ASC 2010

Compact cable



D C van der Laan, X F Lu and L F Goodrich, "Compact GdBa₂Cu₃O_{7-δ} coated conductor cables for electric power transmission and magnet applications", Supercond. Sci. Technol. 24 (2011) 055001

Lecture 8

Summary of potential magnet conductors

	Conductor manufacture	MF?	Shape	Isotropic	n-value	Coil manufacture	Material class
Bi2212 ~80 K >50 T	Powder-in-tube	Pseudo	Tape & Round 300 m	Yes or no	Low	R&W or W&R	Oxide
Bi2223 ~110 K >50 T	Powder-in-tube	Pseudo/ yes	Tape 1.4-2 km	No	Mid	R&W	Oxide
YBCO ~90 K >50 T	Deposition processing	No	Tape 1 km	No	High	R&W	Oxide
MgB ₂ ~39 K 12-40 T	Powder-in-tube	Yes	Round 1 km	Yes	High	R&W or W&R	Boride

“YBCO, Bi2212, ... *what needs to be improved?*”

- Bi2212 (>22 yrs of PIT)
 - Is porosity intrinsic to PIT?
 - Are non-Bi2212 phases avoidable with peritectic melting?
 - Narrow temperature window challenge *in large systems*
 - Lack of strain tolerance
 - Are 100%-dense, 100%-phase pure filaments the answer?
 - AgX needs a better “X”
- YBCO (>15 yrs of CCs)
 - Can we manage the high J_c ?
 - Very different $J(x,y)$
 - Particularly in light of drop-outs
 - High J_e cable? What price?
 - Can high current cable bend?
 - Joining (conductors & cables)